ADC08831/2

Qualification Package

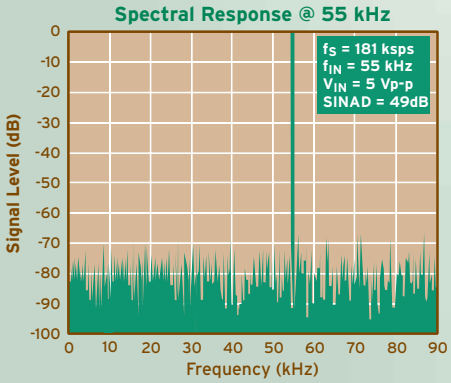
Click Here For ADC08831 Web Info

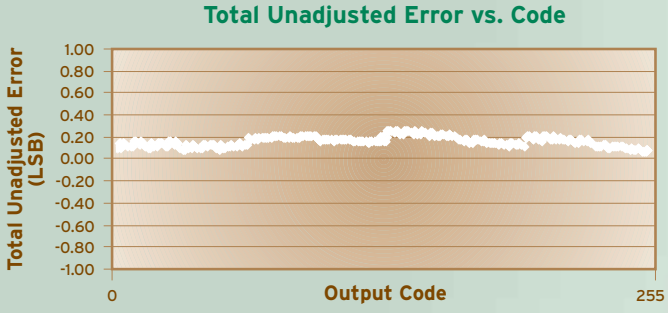
Click Here For ADC08832 Web Info

Single/Dual Channel A/D Converters

National's new A/D Converter is offered in a very small package – the MSOP-8.

- 8-Bit Resolution
- ±1 LSB Linearity
- New Small Package – MSOP-8
  Also available in 8-pin SO and DIP, and 14-pin wide body SO packages
- Fast conversion time
  4µS (max)
- Low power usage
  8.5mW (typ)
- 3-Wire Serial Digital Data Link Requires Few I/O Pins





National Semiconductor

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ADC08831/ADC08832
QUALIFICATION PACKAGE

Spring 1999

Table of Contents

1.0 INTRODUCTION

1.1 General Product Description

The ADC08831 and ADC08832 are a single and 2-channel CMOS Analog-to-Digital Converters. These devices are excellent for a variety of instrumentation and waveform digitization purposes because of their low cost, low power, small footprint and solid industrial specifications.

1.2 Technical Product Description

The ADC08831 and ADC08832 are 8-bit Analog-to-Digital Converters that use a successive approximation register (SAR) architecture. They have excellent linearity performance, with no missing codes over supply and temperature.

These devices operate from a single 5 Volt supply, at a maximum clock frequency of 2 MHz (181 ksps), with low supply current, and a low power mode. A serial output uses a standard MICROWIRE™ interface.

The ADC08831 and ADC08832 are fabricated in an advanced submicron process, with double poly capacitors. The SAR architecture is implemented with a mixed Capacitive and Resistive internal Digital-to-Analog Converter. Double poly capacitors are used for their excellent matching properties, which provide the user with superb linearity performance. Both devices are manufactured identically, except for a metal-2 mask option.

Package choices include the MSOP-8, SO-8, SO-14, and DIP-8.

1.3 Reliability/Qualification Overview

The ADC08831/2 is fabricated using the CS65SP CMOS process. These devices are the first CS65SP products to be packaged in molded DIP, 300 mil SOIC, and MSOP. The qualification plan, therefore, also included package qualifications for each of these package combinations. The 150 mil SOIC package had already been qualified. The package qualifications included autoclave, temperature-humidity bias testing, high temperature storage life, and temperature cycling. All tests were successfully completed. The ADC08832 die itself was qualified by successfully completing 500 hours of dynamic operating life at 150°C. The ADC08831, a metal mask option, qualified by extension. Refer to the reliability reports included in this booklet for more details.

1.4 Technical Assistance

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Fax: 81-3-5639-7507

Asia Pacific
Fax: 65-2504466
Email: sea.support@nsc.com
Tel: 65-2544466
(IDD telephone charge to be paid by caller)

See us on the Worldwide Web @ http://www.national.com

2.0 DEVICE INFORMATION

2.1 Datasheet

National Semiconductor

December 1998

ADC08831/ADC08832
8-Bit Serial I/O CMOS A/D Converters with Multiplexer and Sample/Hold Function

General Description

The ADC08831/ADC08832 are 8-bit successive approximation Analog to Digital converters with 3-wire serial interfaces and a configurable input multiplexer for 2 channels. The serial I/O will interface to COPS™family, PLD's, microprocessors, DSP's, or shift registers. The serial I/O is configured to comply with the NSC MICROWIRE™ serial data exchange standard.

To minimize total power consumption, the ADC08831/ADC08832 automatically go into low power mode whenever they are not performing conversions.

A track/hold function allows the analog voltage at the positive input to vary during the actual A/D conversion.

The analog inputs can be configured to operate in various combination of single-ended, differential, or pseudo-differential modes. The voltage reference input can be adjusted to allow encoding of small analog voltage spans to the full 8-bits of resolution.

Applications

- Digitizing sensors and waveforms
- Process control monitoring
- Remote sensing in noisy environments
- Instrumentation
- Embedded Systems

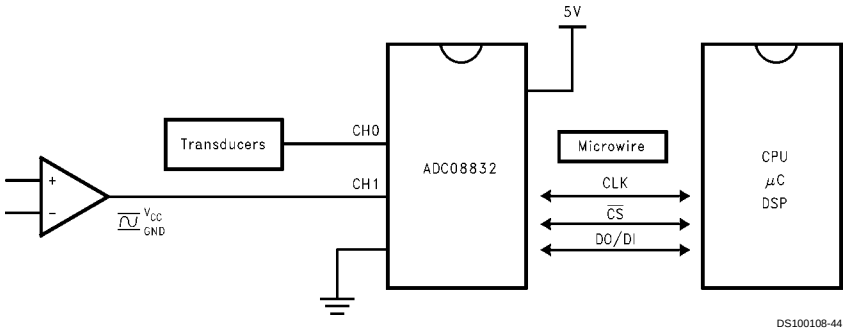
Features

- 3-wire serial digital data link requires few I/O pins
- Analog input track/hold function
- 2-channel input multiplexer option with address logic
- Analog input voltage range from GND to V_{CC}
- No zero or full scale adjustment required
- TTL/CMOS input/output compatible
- Superior pin compatible replacement for ADC0831/2

Key Specifications

- Resolution: 8 bits
- Conversion time (f_C = 2 MHz): 4µs (max)
- Power dissipation: 8.5mW (typ)
- Low power mode 3.0mW (typ)
- Single supply: $5V_{DC}$
- Total unadjusted error: ±1LSB
- No missing codes over temperature

Typical Application



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MICROWIRE™ is a trademark of National Semiconductor Corporation.
TRI-STATE™

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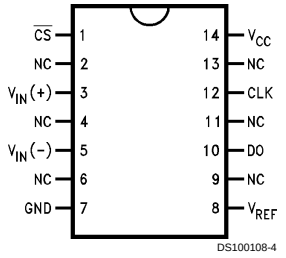
Connection Diagrams

ADC08831
Wide Body SO Packages



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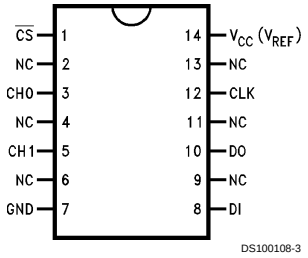
ADC08832
Wide Body SO Packages



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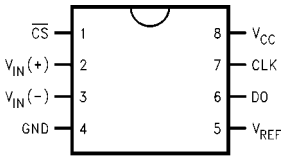
ADC08831
N,M,MM Packages



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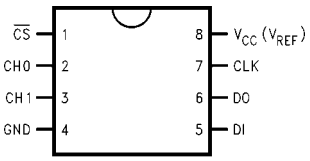
ADC08832
N,M,MM Packages



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Ordering Information

Temperature Range	Package
Industrial (−40˚C ≤ T_J ≤ +85˚C)	
ADC08831IN	N08E
ADC08832IN	
ADC08831IWM,	M14B
ADC08832IWM,	
ADC08831IM,	M08A
ADC08832IM,	
ADC08831IMM,	MUA08A
ADC08832IMM,	

Absolute Maximum Ratings (Notes 1, 3)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/ Distributors for availability and specifications.

Supply Voltage (V_{CC})	6.5V
Voltage at Inputs and Outputs	−0.3V to V_{CC} + 0.3V
Input Current at Any Pin (Note 4)	±5 mA
Package Input Current (Note 4)	±20 mA
ESD Susceptibility (Note 6)	
Human Body Model	2000V
Machine Model	200V
Junction Temperature(Note 5)	150˚C
Storage Temperature Range	−65˚ C to 150˚C
Mounting Temperature	
Lead Temp. (soldering, 10 sec)	260˚C
Infrared (10 sec)	215˚C

Operating Ratings (Notes 2, 3)

Temperature Range	$-40˚C \le T_J \le +85˚C$
Supply Voltage	4.5 V to 6.0 V
Thermal Resistance (θ_{jA})	
SO Package, 8-pin Surface Mount	190˚C/W
MSOP, 8-pin Surface Mount	235˚C/W
SO Package, 14-pin Surface Mount	145˚C/W
N Package, 8-pin	122˚C/W
Clock Frequency	$10kHz \le f_{CLK} \le 2MHz$

Electrical Characteristics

The following specifications apply for $V_{CC} = V_{REF} = +5V_{DC}$, and f_{CLK} = 2 MHz unless otherwise specified. **Boldface limits apply for $T_A = T_J = T_{MIN}$ to T_{MAX};** all other limits $T_A = T_J = 25˚C$.

Symbol	Parameter	Conditions	Typical (Note 8)	Limits (Note 9)	Units (Limits)
CONVERTER AND MULTIPLEXER CHARACTERISTICS					
TUE	Total Unadjusted Error	(Note 10)	±0.3	**±1**	LSB (max)
	Offset Error		±0.2		LSB
DNL	Differential NonLinearity		±0.2		LSB
INL	Integral NonLinearity		±0.2		LSB
FS	Full Scale Error		±0.3		LSB
R_{REF}	Reference Input Resistance	(Note 11)	3.5	**2.8** **5.9**	kΩ (min) kΩ (max)
V_{IN}	Analog Input Voltage	(Note 12)		**(V_{CC} + 0.05)** **(GND − 0.05)**	V (max) V (min)
	DC Common-Mode Error			**±¼**	LSB (max)
	Power Supply Sensitivity	V_{CC} = 5V ±10%, V_{CC} = 5V ±5%		±¼ **±¼**	LSB (max) LSB (max)
	On Channel Leakage Current (Note 13)	On Channel = 5V, Off Channel = 0V		0.2 **1**	µA (max)
		On Channel = 0V Off Channel = 5V		−0.2 **−1**	µA (min)
	Off Channel Leakage Current (Note 13)	On Channel = 5V, Off Channel = 0V		−0.2 **−1**	µA (min)
		On Channel = 0V, Off Channel = 5V		0.2 **1**	µA (max)
DC CHARACTERISTICS					
$V_{IN(1)}$	Logical “1” Input Voltage			**2.0**	V (min)
$V_{IN(0)}$	Logical “0” Input Voltage			**0.8**	V (max)
$I_{IN(1)}$	Logical “1” Input Current	V_{IN} = 5.0V	0.05	**+1**	µA (max)
$I_{IN(0)}$	Logical “0” Input Current	V_{IN} = 0V	0.05	**−1**	µA (max)
$V_{OUT(1)}$	Logical “1” Output Voltage	V_{CC} = 4.75V: I_{OUT} = −360 µA I_{OUT} = −10 µA		 **2.4** **4.5**	 V (min) V (min)
$V_{OUT(0)}$	Logical “0” Output Voltage	V_{CC} = 4.75V I_{OUT} = 1.6 mA		**0.4**	V (max)
I_{OUT}	TRI-STATE Output Current	V_{OUT} = 0V V_{OUT} = 5V		**−3.0** **3.0**	µA (max) µA (max)
I_{SOURCE}	Output Source Current	V_{OUT} = 0V		**−6.5**	mA (max)
I_{SINK}	Output Sink Current	$V_{OUT} = V_{CC}$		**8.0**	mA (min)

Electrical Characteristics (Continued)

The following specifications apply for $V_{CC} = V_{REF} = +5V_{DC}$, and $f_{CLK} = 2$ MHz unless otherwise specified. **Boldface limits apply for $T_A = T_J = T_{MIN}$ to T_{MAX};** all other limits $T_A = T_J = 25^\circ C$.

Symbol	Parameter	Conditions	Typical (Note 8)	Limits (Note 9)	Units (Limits)
DC CHARACTERISTICS					
I_{CC}	Supply Current ADC08831 CLK = high	$\overline{CS}$ = V_{CC}	0.6	**1.0**	mA (max)
		$\overline{CS}$ = LOW	1.7	**2.4**	mA (max)
I_{CC}	Supply Current ADC08832 CLK = high (Note 16)	$\overline{CS}$ = V_{CC}	1.3	**1.8**	mA (max)
		$\overline{CS}$ = LOW	2.4	**3.5**	mA (max)

Electrical Characteristics

The following specifications apply for $V_{CC} = V_{REF} = +5\ V_{DC}$, and $t_r = t_f = 20$ ns unless otherwise specified. **Boldface limits apply for $T_A = T_J = T_{MIN}$ to T_{MAX};** all other limits $T_A = T_J = 25^\circ C$.

Symbol	Parameter	Conditions	Typical (Note 8)	Limits (Note 9)	Units (Limits)
f_{CLK}	Clock Frequency			**2**	MHz (max)
	Clock Duty Cycle (Note 14)			**40** **60**	% (min) % (max)
T_C	Conversion Time (Not Including MUX Addressing Time)	f_{CLK} = 2MHz		**8** **4**	$1/f_{CLK}$ (max) µs (max)
t_{CA}	Acquisition Time			**½**	$1/f_{CLK}$(max)
t_{SET-UP}	$\overline{CS}$ Falling Edge or Data Input Valid to CLK Rising Edge			**25**	ns (min)
t_{HOLD}	Data Input Valid after CLK Rising Edge			**20**	ns (min)
t_{pd1}, t_{pd0}	CLK Falling Edge to Output Data Valid (Note 15)	C_L = 100 pF: Data MSB First Data LSB First		 **250** **200**	 ns (max) ns (max)
t_{1H}, t_{0H}	TRI-STATE Delay from Rising Edge of $\overline{CS}$ to Data Output and SARS Hi-Z	C_L = 10 pF, R_L = 10 kΩ (see TRI-STATE Test Circuits)	50		ns
		C_L = 100 pF, R_L = 2 kΩ		**180**	ns (max)
C_{IN}	Capacitance of Analog input (Note 17)		13		pF
C_{IN}	Capacitance of Logic Inputs		5		pF
C_{OUT}	Capacitance of Logic Outputs		5		pF

Dynamic Characteristics

The following specifications apply for V_{CC} = 5V, f_{CLK} = 2MHz, T_A= 25˚C, R_{SOURCE} = 50Ω, f_{IN} = 45kHz, V_{IN} = $5V_{P-P}$, V_{REF} = 5V, non-coherent 2048 samples with windowing.

Symbol	Parameter	Conditions	Typical (Note 8)	Limits (Note 9)	Units (Limits)
f_S	Sampling Rate ADC08831	f_{CLK}/11		181	ksps
	ADC08832	f_{CLK}/13		153	ksps
SNR	Signal-to -Noise Ratio (Note 19)		48.5		dB
THD	Total Harmonic Distortion (Note 20)		−59.5		dB
SINAD	Signal-to -Noise and Distortion		48.0		dB
ENOB	Effective Number Of Bits (Note 18)		7.7		Bits
SFDR	Spurious Free Dynamic Range		62.5		dB

Note 1: Absolute Maximum Ratings indicate limits beyond which damage to the device may occur.

Note 2: Operating Ratings indicate conditions for which the device is functional. These ratings do not guarantee specific performance limits. For guaranteed specifications and test conditions, see the Electrical Characteristics. The guaranteed specifications apply only for the test conditions listed. Some performance characteristics may degrade when the device is not operated under the listed test conditions.

Note 3: All voltages are measured with respect to GND = 0 V_{DC}, unless otherwise specified.

Note 4: When the input voltage V_{IN} at any pin exceeds the power supplies (V_{IN} < (GND) or V_{IN} > V_{CC},) the current at that pin should be limited to 5 mA. The 20 mA maximum package input current rating limits the number of pins that can safely exceed the power supplies with an input current of 5 mA to four pins.

Note 5: The maximum power dissipation must be derated at elevated temperatures and is dictated by T_{JMAX}, θ_{JA} and the ambient temperature, T_A. The maximum allowable power dissipation at any temperature is $P_D = (T_{JMAX} - T_A)/\theta_{JA}$ or the number given in the Absolute Maximum Ratings, whichever is lower.

Note 6: Human body model, 100 pF capacitor discharged through a 1.5 kΩ resistor. The machine mode is a 200pF capacitor discharged directly into each pin.

Note 7: See AN450 “Surface Mounting Methods and Their Effect on Product Reliability” or Linear Data Book section “Surface Mount” for other methods of soldering surface mount devices.

Note 8: Typicals are at T_J = 25˚C and represent the most likely parametric norm.

Note 9: Guaranteed to National’s AOQL (Average Outgoing Quality Level).

Note 10: Total unadjusted error includes offset, full-scale, linearity, multiplexer errors.

Note 11: It is not tested for the ADC08832.

Note 12: For $V_{IN(-)} \geq V_{IN(+)}$ the digital code will be 0000 0000. Two on-chip diodes are tied to each analog input (see Functional Block Diagram) which will forward-conduct for analog input voltages one diode drop below ground or one diode drop greater than V_{CC} supply. During testing at low V_{CC} levels (e.g., 4.5V), high level analog inputs (e.g., 5V) can cause an input diode to conduct, especially at elevated temperatures, which will cause errors for analog inputs near full-scale. The spec allows 50 mV forward bias of either diode; this means that as long as the analog V_{IN} does not exceed the supply voltage by more than 50 mV, the output code will be correct. Exceeding this range on an unselected channel will corrupt the reading of a selected channel. Achievement of an absolute 0 V_{DC} to 5 V_{DC} input voltage range will therefore require a minimum supply voltage of 4.950 V_{DC} over temperature variations, initial tolerance and loading.

Note 13: Channel leakage current is measured after a single-ended channel is selected and the clock is turned off. For off channel leakage current the following two cases are considered: one, with the selected channel tied high (5 V_{DC}) and the remaining off channel tied low (0 V_{DC}), total current flow through the off channel is measured; two, with the selected channel tied low and the off channels tied high, total current flow through the off channel is again measured. The two cases considered for determining on channel leakage current are the same except total current flow through the selected channel is measured.

Note 14: A 40% to 60% duty cycle range insures proper operation at all clock frequencies. In the case that an available clock has a duty cycle outside of these limits the minimum time the clock is high or low must be at least 250 ns. The maximum time the clock can be high or low is 60 µs.

Note 15: Since data, MSB first, is the output of the comparator used in the successive approximation loop, an additional delay is built in to allow for comparator response time.

Note 16: For the ADC08832 V_{ref} is internally tied to V_{CC}, therefore, for the ADC08832 reference current is included in the supply current.

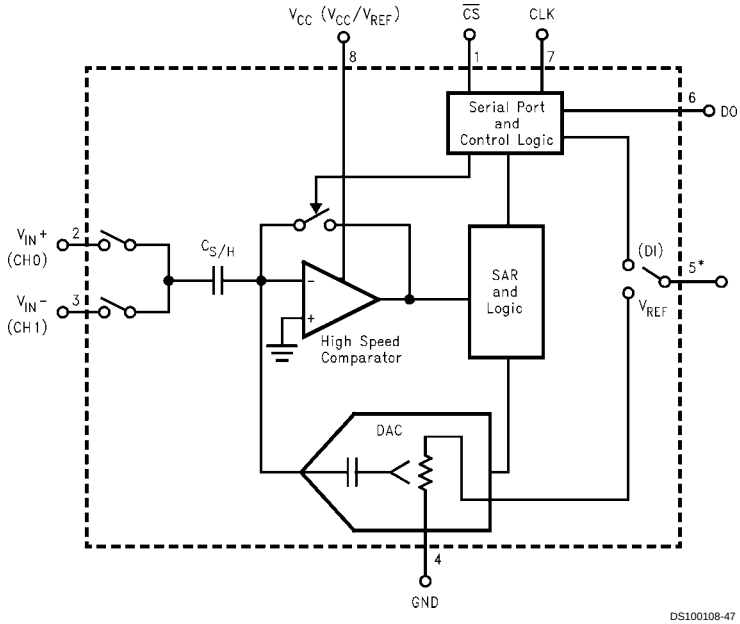
Note 17: Analog inputs are typically 300 ohms input resistance to a 13pF sample and hold.

Note 18: Effective Number Of Bits (ENOB) is calculated from the measured signal-to-noise plus distortion ratio (SINAD) using the equation ENOB = (SINAD-1.76)/6.02.

Note 19: The signal-to-noise ratio is the ratio of the signal amplitude to the background noise level. Harmonics of the input signal are not included in it’s calculation.

Note 20: The contributions from the first 6 harmonics are used in the calculation of the THD.

Block Diagram

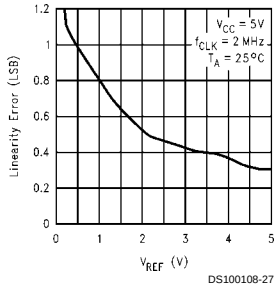


*For ADC08831 V_{REF} pin is available, for ADC08832 DI pin is available, and V_{REF} is tied to V_{CC}
Pin names in parentheses refer to ADC08832

Typical Performance Characteristics

The following specifications apply for T_A = 25°C, V_{CC} = V_{REF} = 5V, unless otherwise specified.

Linearity Error (TUE) vs Reference Voltage



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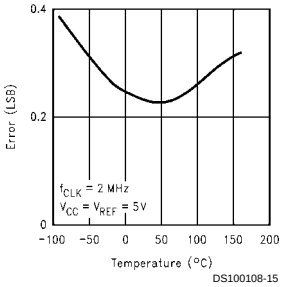
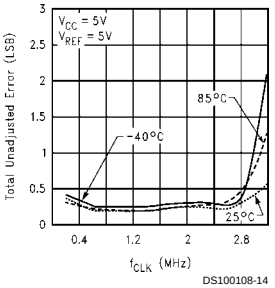
Linearity Error (TUE) vs Temperature



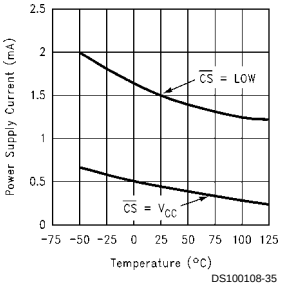
DS100108-15

Linearity Error (TUE) vs Clock Frequency



DS100108-14

Power Supply Current vs Temperature (ADC08831)



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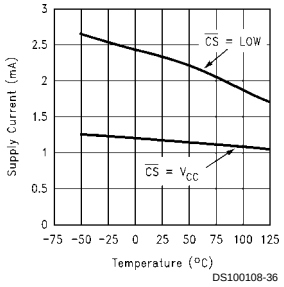
Power Supply Current vs Temperature (ADC08832)



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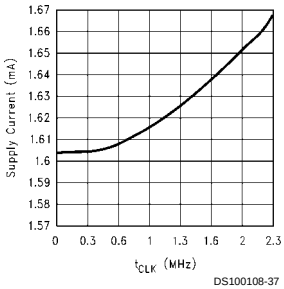
Power Supply Current vs Clock Frequency, $\overline{CS}$ = Low, ADC08831



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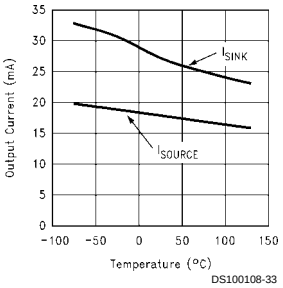
Output Current vs Temperature

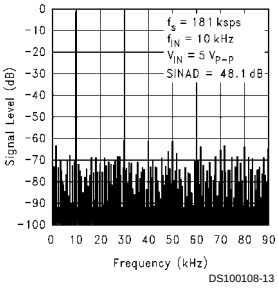


DS100108-33

Typical Performance Characteristics

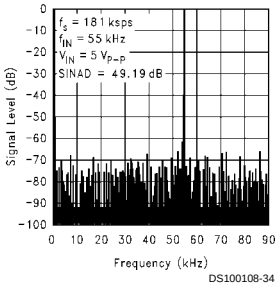
The following specifications apply for T_A = 25˚C, V_{CC} = V_{REF} = 5V, unless otherwise specified. (Continued)

Spectral Response with 10KHz Sine Wave Input



DS100108-13

Spectral Response with 55 KHz Sine Wave Input



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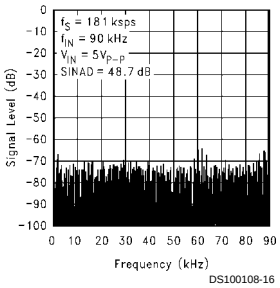
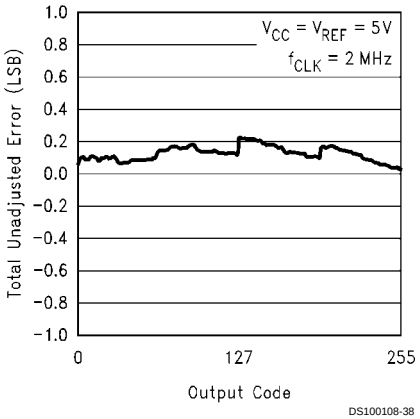
Spectral Response with 90 KHz Sine Wave Input



DS100108-16

Total Unadjuster Error Plot



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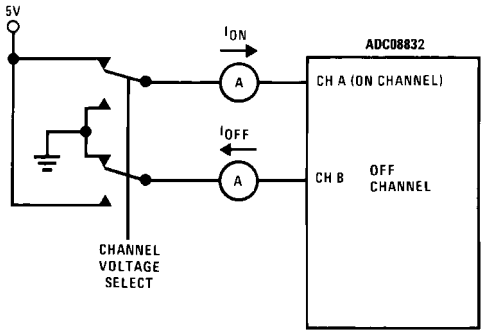
Leakage Current Test Circuit



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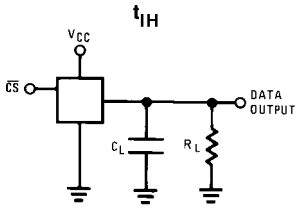
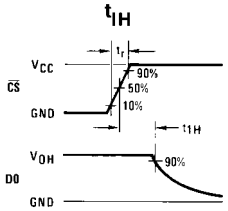
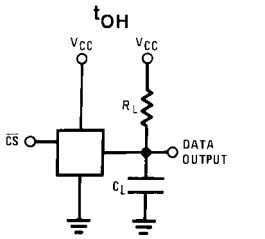
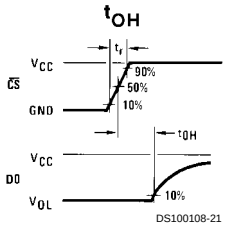
TRI-STATE Test Circuits and Waveforms







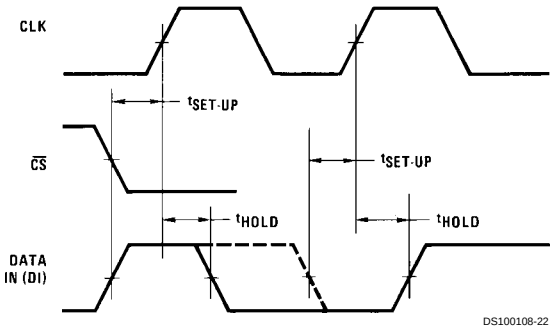
DS100108-20



DS100108-21

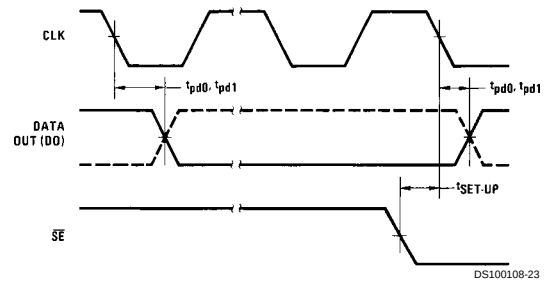
Timing Diagrams

Data Input Timing



DS100108-22

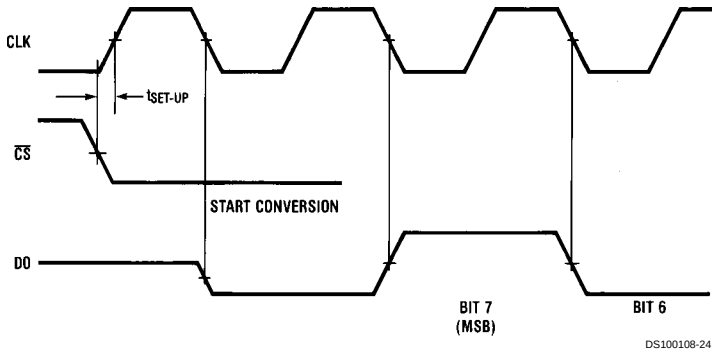
Data Output Timing



DS100108-23

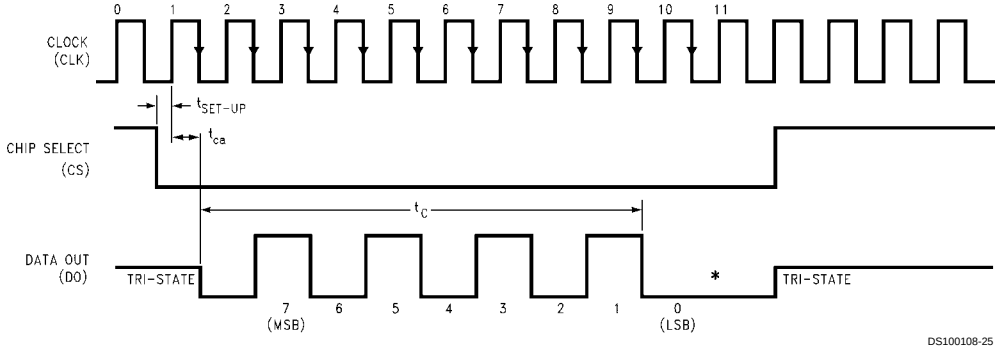
Timing Diagrams (Continued)

ADC08831 Start Conversion Timing



DS100108-24

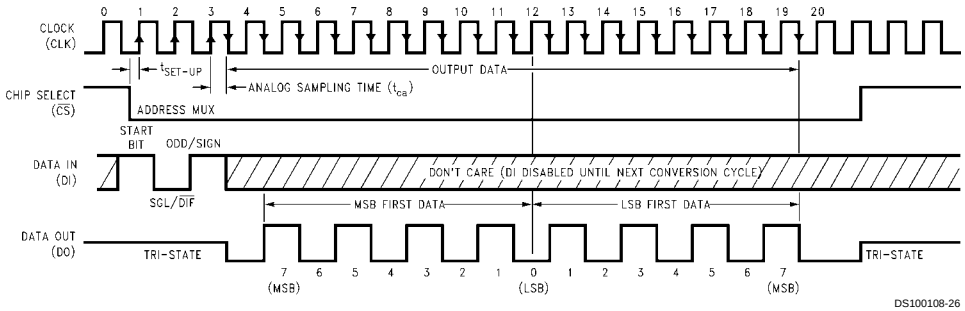
ADC08831 Timing



DS100108-25

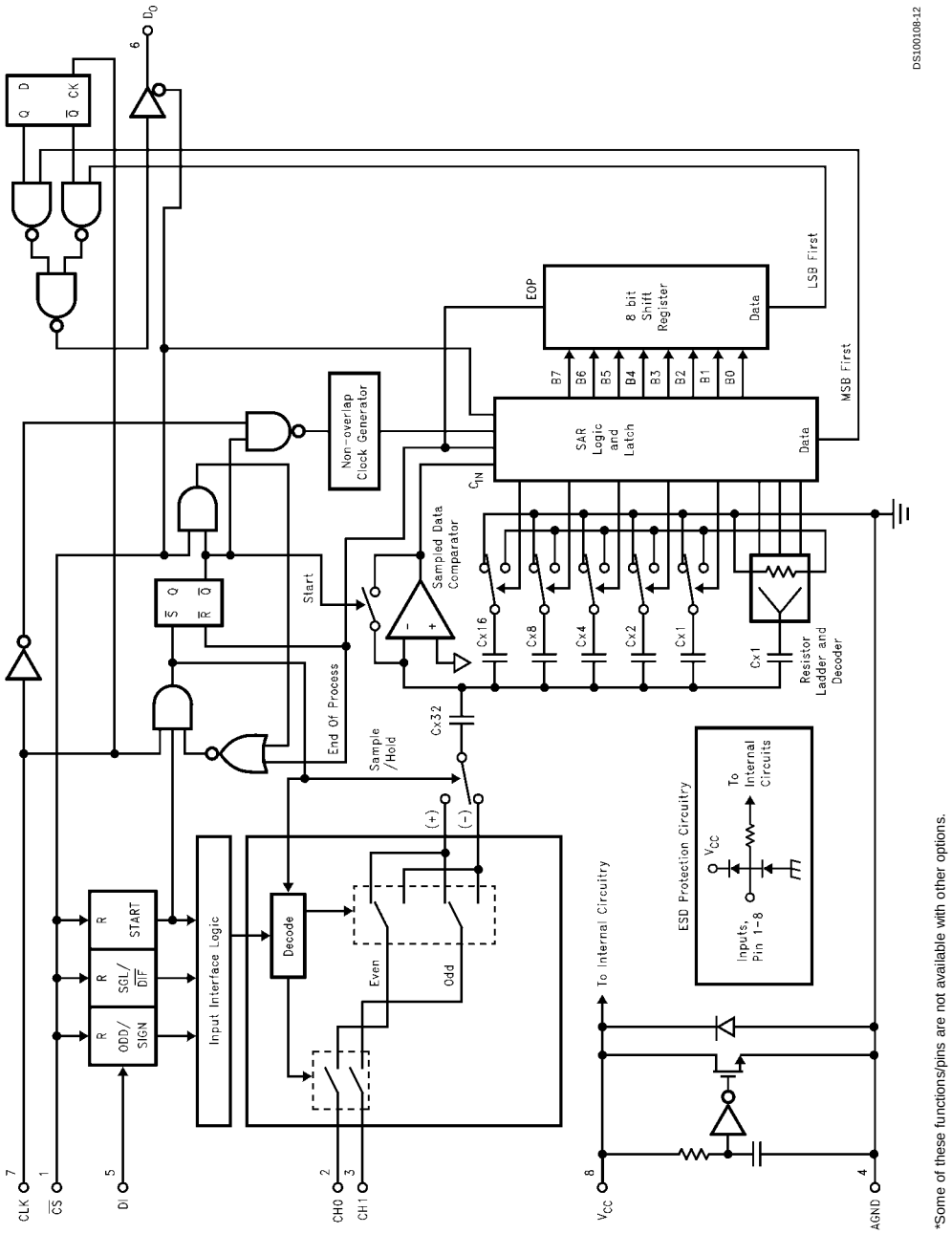
*LSB first output not available on ADC08831.

ADC08832 Timing



DS100108-26

ADC08832 Functional Block Diagram



Functional Description

1.0 MULTIPLEXER ADDRESSING

The design of these converters utilizes a comparator structure with built-in sample-and-hold which provides for a differential analog input to be converted by a successive approximation routine.

The actual voltage converted is always the difference between an assigned "+" input terminal and a "−" input terminal. The polarity of each input terminal of the pair indicates which line the converter expects to be the most positive. If the assigned "+" input voltage is less than the "−" input voltage the converter responds with an all zeros output code.

A unique input multiplexing scheme has been utilized to provide multiple analog channels with software-configurable single-ended, or differential operation. The analog signal conditioning required in transducer-based data acquisition systems is significantly simplified with this type of input flexibility. One converter package can now handle ground referenced inputs, differential inputs, as well as signals with some arbitrary reference voltage.

A particular input configuration is assigned during the MUX addressing sequence, prior to the start of a conversion. The MUX address selects which of the analog inputs are to be enabled and whether this input is single-ended or differential. In addition to selecting differential mode the polarity may also be selected. Channel 0 may be selected as the positive input and channel 1 as the negative input or vice versa. This programmability is illustrated by the MUX addressing codes for the ADC08832.

The MUX address is shifted into the converter via the DI line. Because the ADC08831 contains only one differential input channel with a fixed polarity assignment, it does not require addressing.

TABLE 1. Multiplexer/Package Options

Part Number	Number of Analog Channels		Number of Package Pins
	Single-Ended	Differential	
ADC08831	1	1	8 or 14
ADC08832	2	1	8 or 14

MUX Addressing: ADC08832

Single-Ended MUX Mode				
MUX Address			Channel #	
Start Bit	SGL/$\overline{\text{DIF}}$	ODD/ SIGN	0	1
1	1	0	+	
1	1	1		+

Differential MUX Mode				
MUX Address			Channel #	
Start Bit	SGL/$\overline{\text{DIF}}$	ODD/ SIGN	0	1
1	0	0	+	−
1	0	1	−	+

Since the input configuration is under software control, it can be modified as required before each conversion. A channel can be treated as a single-ended, ground referenced input for one conversion; then it can be reconfigured as part of a differential channel for another conversion.

The analog input voltages for each channel can range from 50mV below ground to 50mV above V_{CC} (typically 5V) without degrading conversion accuracy.

2.0 THE DIGITAL INTERFACE

A most important characteristic of these converters is their serial data link with the controlling processor. Using a serial communication format offers two very significant system improvements. It allows many functions to be included in a small package and it can eliminate the transmission of low level analog signals by locating the converter right at the analog sensor; transmitting highly noise immune digital data back to the host processor.

To understand the operation of these converters it is best to refer to the Timing Diagrams and Functional Block Diagram and to follow a complete conversion sequence. For clarity, a separate timing diagram is shown for each device.

1. A conversion is initiated by pulling the $\overline{\text{CS}}$ (chip select) line low. This line must be held low for the entire conversion. The converter is now waiting for a start bit and its MUX assignment word, if applicable.
2. On each rising edge of the clock the status of the data in (DI) line is clocked into the MUX address shift register. The start bit is the first logic "1" that appears on this line (all leading zeros are ignored). Following the start bit the converter expects the next 2 bits to be the MUX assignment word.
3. When the start bit has been shifted into the start location of the MUX register, and the input channel has been assigned, a conversion is about to begin. An interval of ½ clock period (where nothing happens) is automatically inserted to allow the selected MUX channel to settle to a final analog input value. The DI line is disabled at this time. It no longer accepts data.
4. The data out (DO) line now comes out of TRI-STATE and provides a leading zero for this one clock period of MUX settling time.
5. During the conversion the output of the SAR comparator indicates whether the analog input is greater than (high) or less than (low) a series of successive voltages generated internally from a ratioed capacitor array (first 5 bits) and a resistor ladder (last 3 bits). After each comparison the comparator's output is shipped to the DO line on the falling edge of CLK. This data is the result of the conversion being shifted out (with the MSB first) and can be read by the processor immediately.
6. After 8 clock periods the conversion is completed.
7. The stored data in the successive approximation register is loaded into an internal shift register. The data, LSB first, is automatically shifted out the DO line after the MSB first data stream. The DO line then goes low and stays low until $\overline{\text{CS}}$ is returned high. The ADC08831 is an exception in that its data is only output in MSB first format.
8. The DI and DO lines can be tied together and controlled through a bidirectional processor I/O bit with one wire. This is possible because the DI input is only "looked-at" during the MUX addressing interval while the DO line is still in a high impedance state.

Functional Description (Continued)

3.0 Reducing Power Consumption

The ADC08831 operate up to a 2MHz clock frequency, or about 181 ksps. At 5V supply, it consumes about 1.7 mA or 8.5 mW when $\overline{CS}$ is logic low. The ADC08831 has a low power mode to minimize total power consumption.

When the chip select is asserted with a logic high, some analog circuitry and digital logic are pulled to a static, low power condition. Also, DOUT, the output driver is taken into TRI-STATE mode.

To optimize static power consumption, special attention is needed to the digital input logic signals: CLK, $\overline{CS}$, DI. Each digital input has a large CMOS buffer between V_{CC} and GND. A traditional TTL level high (2.4V) will be sufficient for each input to read a logical "1". However, there could be a large V_{IH} to V_{CC} voltage difference at each input. Such a voltage difference would cause static power dissipation, even when chip select pin is high and the part is in low power mode.

Therefore, to minimize static power dissipation, it is recommended that all digital input logic levels should equal the converter's supply. Various CMOS logic is particularly well suited for this application.

The reference pin on the ADC08831 is not affected by the power-down mode. To reduce static reference current during non-conversion time, there are a couple options. First, a low voltage external reference (ie, 2.5V could be used). A shunt reference, such as the LM385-2.5, could be powered by a logic gate that is the inverse of the signal on $\overline{CS}$. When $\overline{CS}$ is high, the reference is off. As a second option, an external, low on-resistance switch could be used.

The ADC08832 is similar to the ADC08831, except its reference is derived from V_{CC}. The ADC08832 does enter a low-power mode when $\overline{CS}$ is logic high, as the analog and digital logic enter static current modes. However power dissipation from the reference ladder occurs, regardless of the signal on $\overline{CS}$

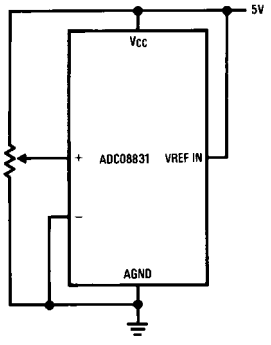
4.0 REFERENCE CONSIDERATIONS

The voltage applied to the reference input on these converters, V_{REF}, defines the voltage span of the analog input (the difference between $V_{IN(MAX)}$ and $V_{IN(MIN)}$ over which the 256 possible output codes apply. The devices can be used either in ratiometric applications or in systems requiring absolute accuracy. The reference pin must be connected to a voltage source capable of driving the reference input resistance which can be as low as 2.8kΩ. This pin is the top of a resistor divider string and capacitor array used for the successive approximation conversion.

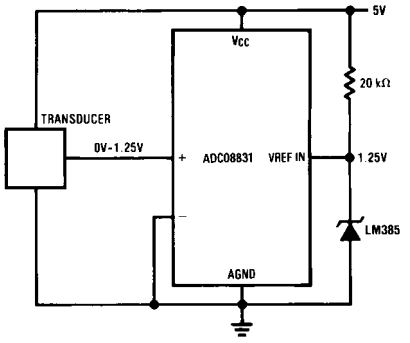
In a ratiometric system the analog input voltage is proportional to the voltage used for the A/D reference. This voltage is typically the system power supply, so the V_{REF} pin can be tied to V_{CC} (done internally on the ADC08832). This technique relaxes the stability requirements of the system reference as the analog input and A/D reference move together maintaining the same output code for a given input condition.

For absolute accuracy, where the analog input varies between very specific voltage limits, the reference pin can be biased with a time and temperature stable voltage source. The LM385, LM336 and LM4040 reference diodes are good low current devices to use with these converters.

The maximum value of the reference is limited to the V_{CC} supply voltage. The minimum value, however, can be quite small (see Typical Performance Characteristics) to allow direct conversions of transducer outputs providing less than a 5V output span. Particular care must be taken with regard to noise pickup, circuit layout and system error voltage sources when operating with a reduced span due to the increased sensitivity of the converter (1 LSB equals $V_{REF}/256$).



a) Ratiometric



b) Absolute with a Reduced Span

FIGURE 1. Reference Examples

Functional Description (Continued)

5.0 THE ANALOG INPUTS

The most important feature of these converters is that they can be located right at the analog signal source and through just a few wires can communicate with a controlling processor with a highly noise immune serial bit stream. This in itself greatly minimizes circuitry to maintain analog signal accuracy which otherwise is most susceptible to noise pickup. However, a few words are in order with regard to the analog inputs should the input be noisy to begin with or possibly riding on a large common-mode voltage.

The differential input of these converters actually reduces the effects of common-mode input noise, a signal common to both selected "+" and "−" inputs for a conversion (60 Hz is most typical). The time interval between sampling the "+" input and then the "−" input is ½ of a clock period. The change in the common-mode voltage during this short time interval can cause conversion errors. For a sinusoidal common-mode signal this error is:

$$V_{error}(max) = V_{PEAK}(2\pi f_{CM})\left(\frac{0.5}{f_{CLK}}\right)$$

where f_{CM} is the frequency of the common-mode signal,

V_{PEAK} is its peak voltage value

and f_{CLK} is the A/D clock frequency.

For a 60Hz common-mode signal to generate a ¼ LSB error (≈5mV) with the converter running at 250kHz, its peak value would have to be 6.63V which would be larger than allowed as it exceeds the maximum analog input limits.

Source resistance limitation is important with regard to the DC leakage currents of the input multiplexer. Bypass capacitors should not be used if the source resistance is greater than 1kΩ. The worst-case leakage current of ±1µA over temperature will create a 1mV input error with a 1kΩ source resistance. An op amp RC active low pass filter can provide both impedance buffering and noise filtering should a high impedance signal source be required.

5.1 Sample and Hold

The ADC08831/2 provide a built-in sample-and-hold to acquire the input signal. The sample and hold can sample input signals in either single-ended or pseudo differential mode.

5.2 Input Op Amps

When driving the analog inputs with an op amp it is important that the op amp settle within the allowed time. To achieve the full sampling rate, the analog input should be driven with a low impedance source (100Ω) or a high-speed op amp such as the LM6142. Higher impedance sources or slower op amps can easily be accommodated by allowing more time for the analog input to settle.

5.3 Source Resistance

The analog inputs of the ADC08831/2 look like a 13pF capacitor (C_{IN}) in series with 300Ω resistor (Ron). C_{IN} gets switched between the selected "+" and "−" inputs during each conversion cycle. Large external source resistors will slow the settling of the inputs. It is important that the overall RC time constants be short enough to allow the analog input to completely settle.

5.4 Board layout Consideration, grounding and bypassing:

The ADC08831/2 are easy to use with some board layout consideration. They should be used with an analog ground plane and single-point grounding techniques. The GND pin should be tied directly to the ground plane.

The supply pin should be bypassed to the ground plane with a surface mount or ceramic capacitor with leads as short as possible. All analog inputs should be referenced directly to the single-point ground. Digital inputs and outputs should be shielded from and routed away from the reference and analog circuitry.

6.0 OPTIONAL ADJUSTMENTS

6.1 Zero Error

The offset of the A/D does not require adjustment. If the minimum analog input voltage value, $V_{IN(MIN)}$, is not ground a zero offset can be done. The converter can be made to output 0000 0000 digital code for this minimum input voltage by biasing any V_{IN} (−) input at this $V_{IN(MIN)}$ value. This utilizes the differential mode operation of the A/D.

The zero error of the A/D converter relates to the location of the first riser of the transfer function and can be measured by grounding the V_{IN} (−) input and applying a small magnitude positive voltage to the V_{IN} (+) input. Zero error is the difference between the actual DC input voltage which is necessary to just cause an output digital code transition from 0000 0000 to 0000 0001 and the ideal ½ LSB value (½ LSB = 9.8mV for V_{REF} = 5.000V_{DC}).

6.2 Full Scale

The full-scale adjustment can be made by applying a differential input voltage which is 1½ LSB down from the desired analog full-scale voltage range and then adjusting the magnitude of the V_{REF} input (or V_{CC} for the ADC08832) for a digital output code which is just changing from 1111 1110 to 1111 1111.

6.3 Adjusting for an Arbitrary Analog Input Voltage Range

If the analog zero voltage of the A/D is shifted away from ground (for example, to accommodate an analog input signal which does not go to ground), this new zero reference should be properly adjusted first. A V_{IN} (+) voltage which equals this desired zero reference plus ½ LSB (where the LSB is calculated for the desired analog span, using 1 LSB = analog span/256) is applied to selected "+" input and the zero reference voltage at the corresponding "−" input should then be adjusted to just obtain the 00_{HEX} to 01_{HEX} code transition.

The full-scale adjustment should be made [with the proper V_{IN} (−) voltage applied] by forcing a voltage to the V_{IN} (+) input which is given by:

$$V_{IN}(+)\,\text{fs adj} = V_{MAX} - 1.5\left[\frac{(V_{MAX} - V_{MIN})}{256}\right]$$

where:

V_{MAX} = the high end of the analog input range

and

V_{MIN} = the low end (the offset zero) of the analog range.

(Both are ground referenced.)

Functional Description (Continued)

The V_{REF}IN (or V_{CC}) voltage is then adjusted to provide a code change from FE_{HEX} to FF_{HEX}. This completes the adjustment procedure.

7.0 DYNAMIC PERFORMANCE

Dynamic performance specifications are often useful in applications requiring waveform sampling and digitization. Typically, a memory buffer is used to capture a stream of consecutive digital outputs for post processing. Capturing a number of samples that is a power of 2 (ie, 1024, 2048, 4096) allows the Fast Fourier Transform (FFT) to be used to digitally analyze the frequency components of the signal. Depending on the application, further digital filtering, windowing, or processing can be applied.

7.1 Sampling Rate

The Sampling Rate, sometimes referred to as the Throughput Rate, is the time between repetitive samples by an Analog-to-Digital Converter. The sampling rate includes the conversion time, as well as other factors such a MUX setup time, acquisition time, and interfacing time delays. Typically, the sampling rate is specified in the number of samples taken per second, at the maximum Analog-to-Digital Converter clock frequency.

Signals with frequencies exceeding the Nyquist frequency (1/2 the sampling rate), will be aliased into frequencies below the Nyquist frequency. To prevent signal degradation, sample at twice (or more) than the input signal and/or use of a low pass (anti-aliasing) filter on the front-end. Sampling at a much higher rate than the input signal will reduce the requirements of the anti-aliasing filter.

Some applications require under-sampling the input signal. In this case, one expects the fundamental to be aliased into the frequency range below the Nyquist frequency. In order to be assured the frequency response accurately represents a harmonic of the fundamental, a band-pass filter should be used over the input range of interest.

7.2 Signal-to-Noise Ratio

Signal-to-Noise Ratio (SNR) is the ratio of RMS magnitude of the fundamental to the RMS sum of all the non-fundamental signal, excluding the harmonics, up to 1/2 of the sampling frequency (Nyquist).

7.3 Total Harmonic Distortion

Total Harmonic distortion is the ratio of the RMS sum of the amplitude of the harmonics to the fundamental input frequency.

$$THD = 20 \log [(V_2^2 + V_3^2 + V_4^2 + V_5^2 + V_6^2)^{1/2} / V_1]$$

Where V_1 is the RMS amplitude of the fundamental and V_2,V_3, V_4, V_5, V_6 are the RMS amplitudes of the individual harmonics. In theory, all harmonics are included in THD calculations, but in practice only about the first 6 make significant contributions and require measurement.

For under-sampling applications, the input signal should be band pass filtered (BPF) to prevent out of band signals, or their harmonics, to appear in the spectral response.

The DC Linearity transfer function of an Analog-to-Digital Converter tends to influence the dominant harmonics. A parabolic Linearity curve would tend to create 2nd (and even) order harmonics, while an S-curve would tend to create 3rd (or odd) order harmonics. The magnitude of an DC linearity error correlates to the magnitude of the harmonics.

7.4 Signal-to-Noise And Distortion

Signal-to-Noise And Distortion ratio (SINAD) is the ratio of RMS magnitude of the fundamental to the RMS sum of all the non-fundamental signals, including the noise and harmonics, up to 1/2 of the sampling frequency (Nyquist), excluding DC.

SINAD is also dependent on the number of quantization levels in the A/D Converter used in the waveform sampling process. The more quantization levels, the smaller the quantization noise and theoretical noise performance. The theoretical SINAD for a N-Bit Analog-to-Digital Converter is given by:

$$SINAD = (6.02\ N + 1.76)\ dB$$

Thus, for an 8-bit converter, the ideal SINAD = 49.92 dB

7.5 Effective Number Of Bits

Effective Number Of Bits (ENOB) is another specification to quantify dynamic performance. The equation for ENOB is given by:

$$ENOB = [(SINAD - 1.76)] / 6.02]$$

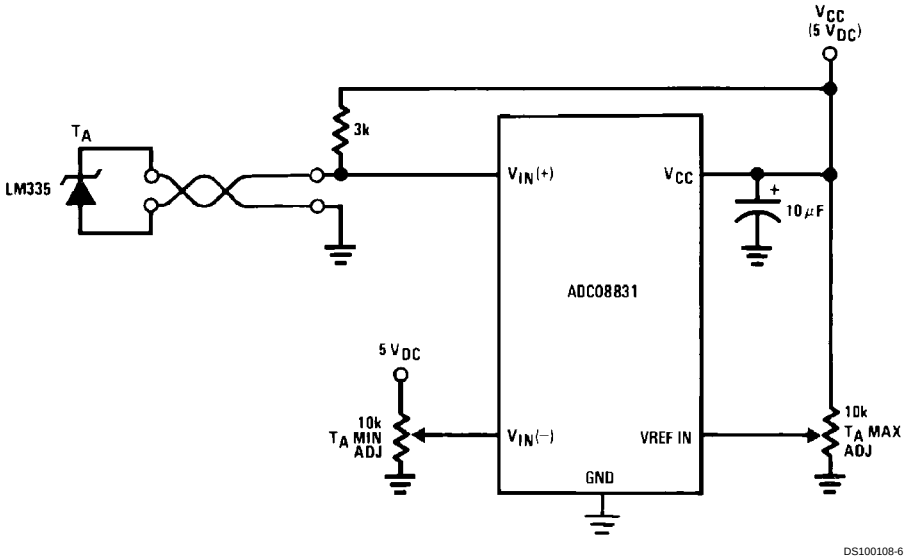
The Effective Number Of Bits portrays the cumulative effect of several errors, including as quantization, non-linearities, noise, and distortion.

7.6 Spurious Free Dynamic Range

Spurious Free Dynamic Range (SFDR) is the ratio of the signal amplitude to the amplitude of the highest harmonic or spurious noise component. If the amplitude is at full scale, the specification is simply the reciprocal of the peak harmonic or spurious noise.

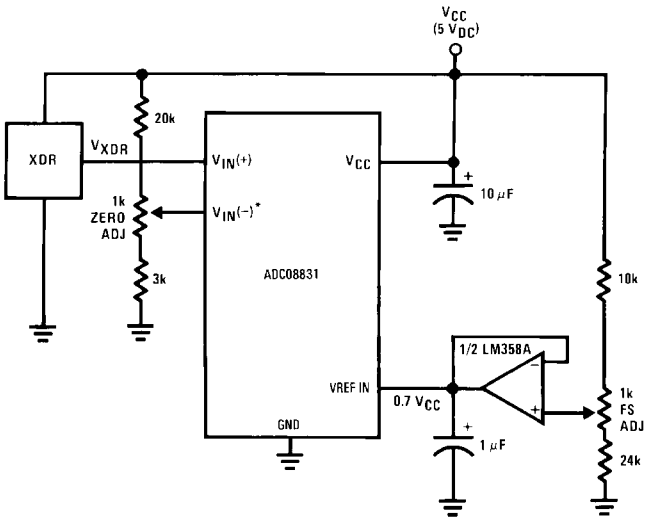
Applications

Low-Cost Remote Temperature Sensor



DS100108-6

Operating with Ratiometric Transducers

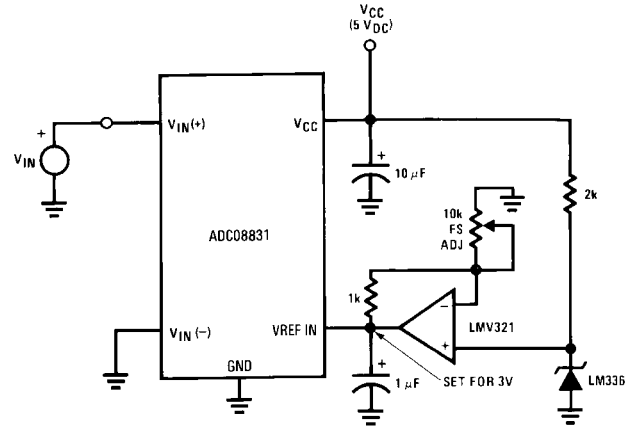


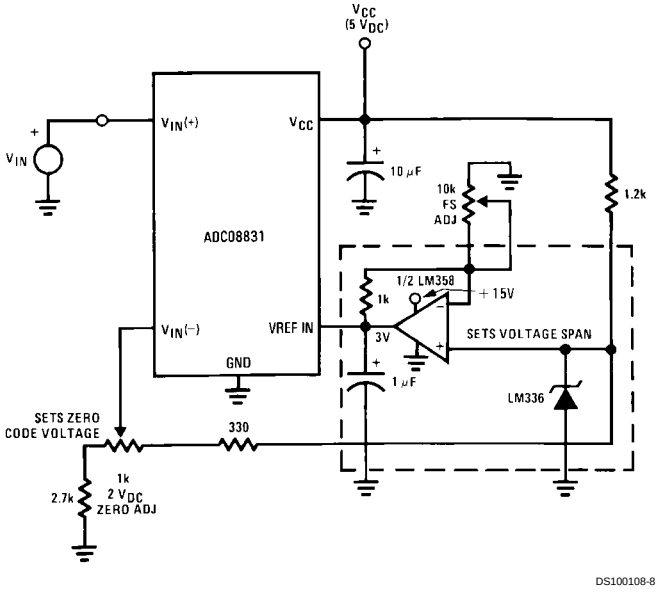
DS100108-7

*$V_{IN}(-)$ = 0.15 V_{CC}
15% of $V_{CC} \leq V_{XDR} \leq$ 85% of V_{CC}

Applications (Continued)

Span Adjust; 0V ≤ V_{IN} ≤ 3V



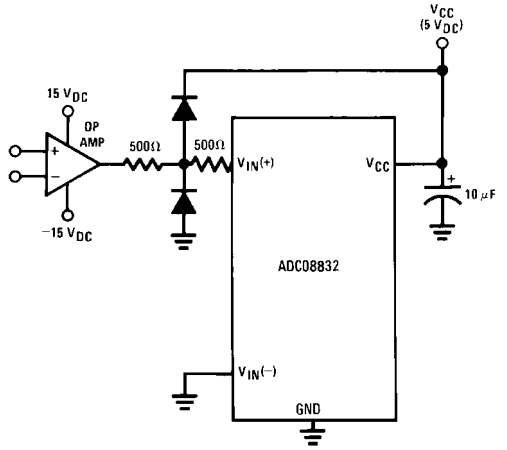


DS100108-8

Zero-Shift and Span Adjust: 2V≤V_{IN} ≤ 5V

Applications (Continued)

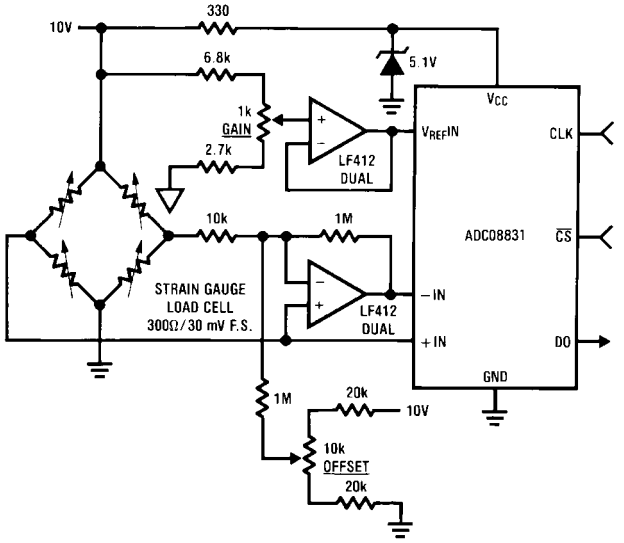
Protecting the Input



DS100108-9

Diodes are 1N914

Digital Load Cell

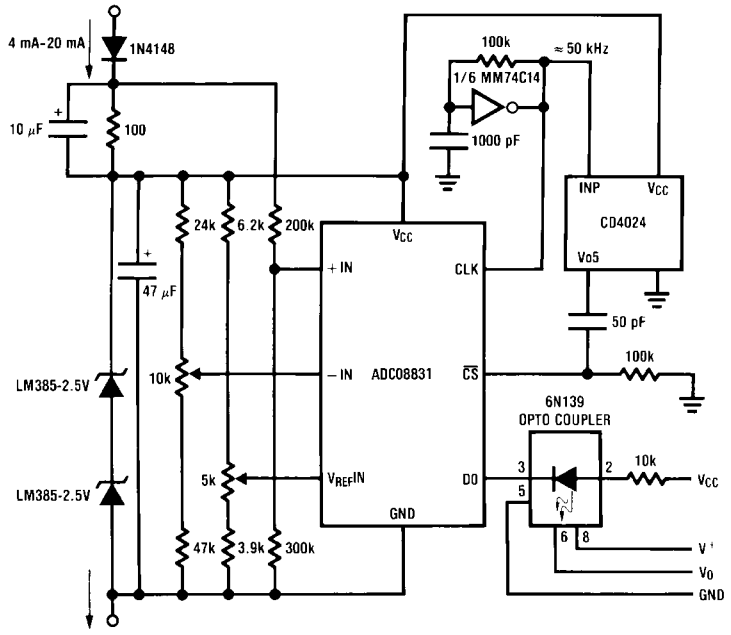


DS100108-10

- Uses one more wire than load cell itself
- Two mini-DIPs could be mounted inside load cell for digital output transducer
- Electronic offset and gain trims relax mechanical specs for gauge factor and offset
- Low level cell output is converted immediately for high noise immunity

Applications (Continued)

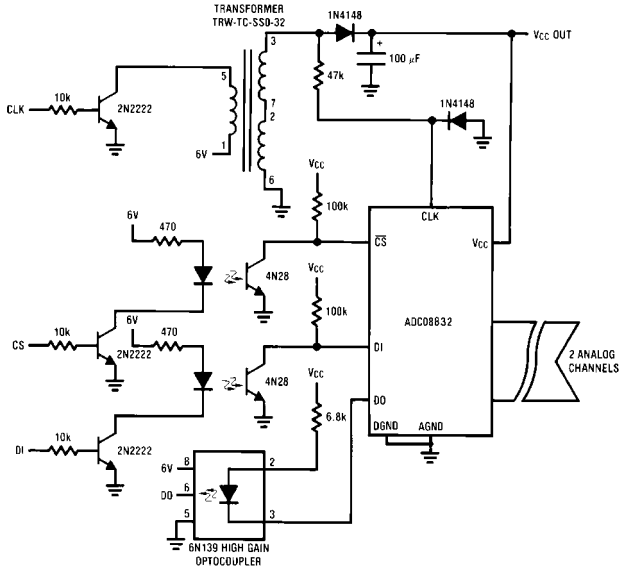
4 mA-20 mA Current Loop Converter



DS100108-11

- All power supplied by loop
- 1500V isolation at output

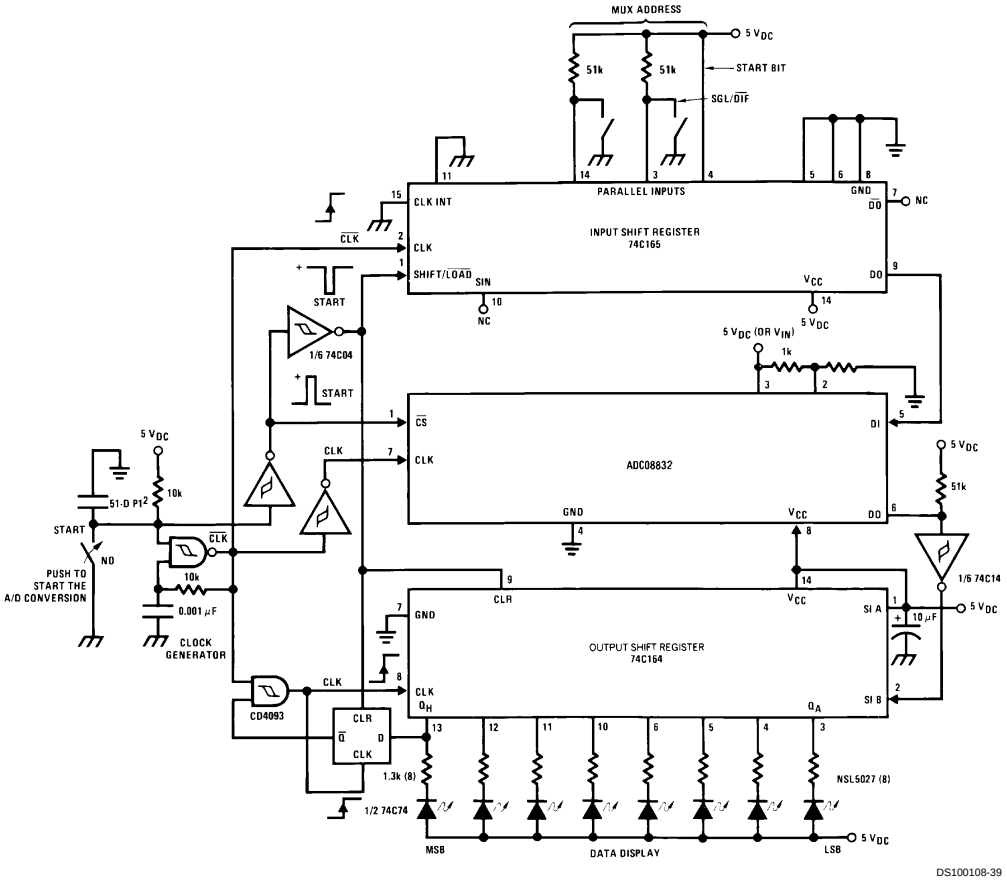
Isolated Data Converter



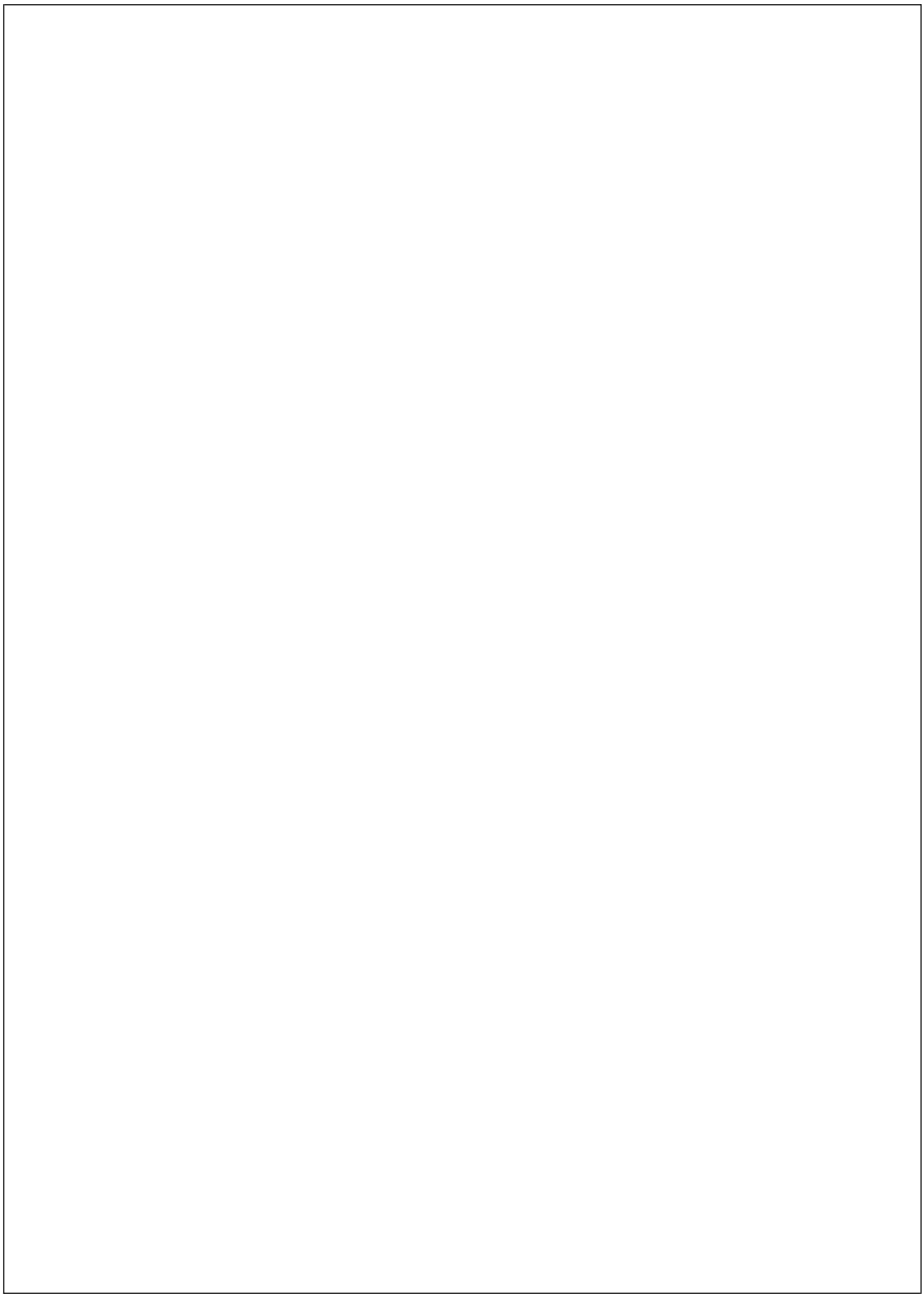
DS100108-40

Applications (Continued)

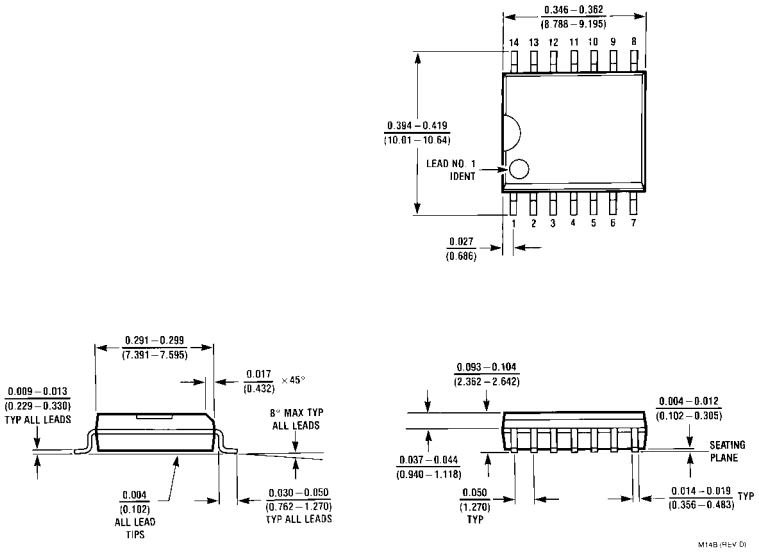
A "Stand-Alone" Hook-Up for ADC08832 Evaluation



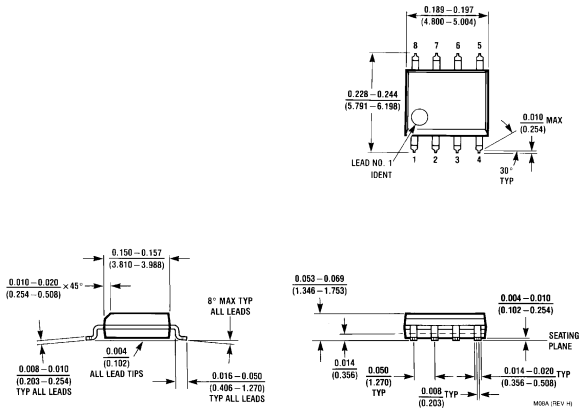
DS100108-39



Physical Dimensions inches (millimeters) unless otherwise noted

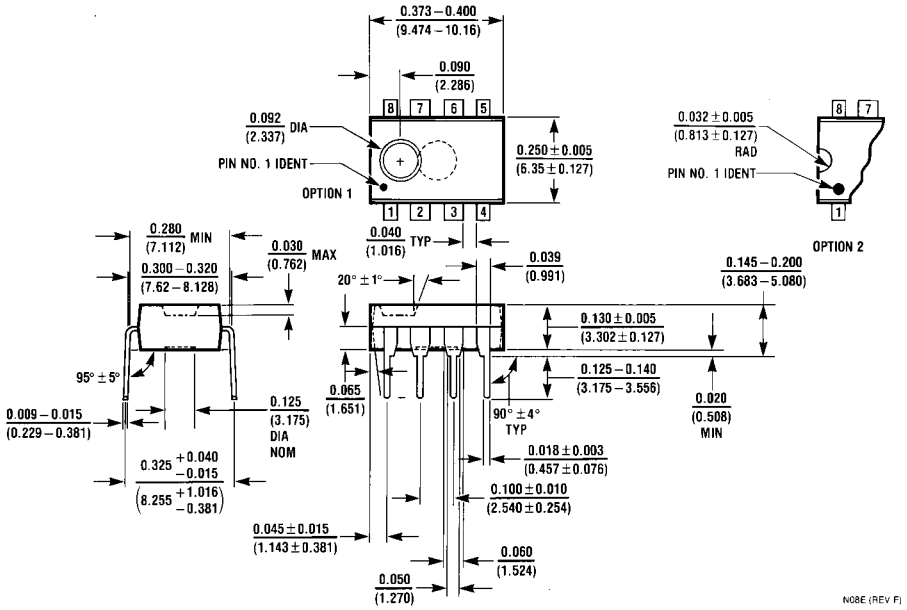


Order Number ADC08831IWM, ADC08832IWM,
NS Package Number M14B



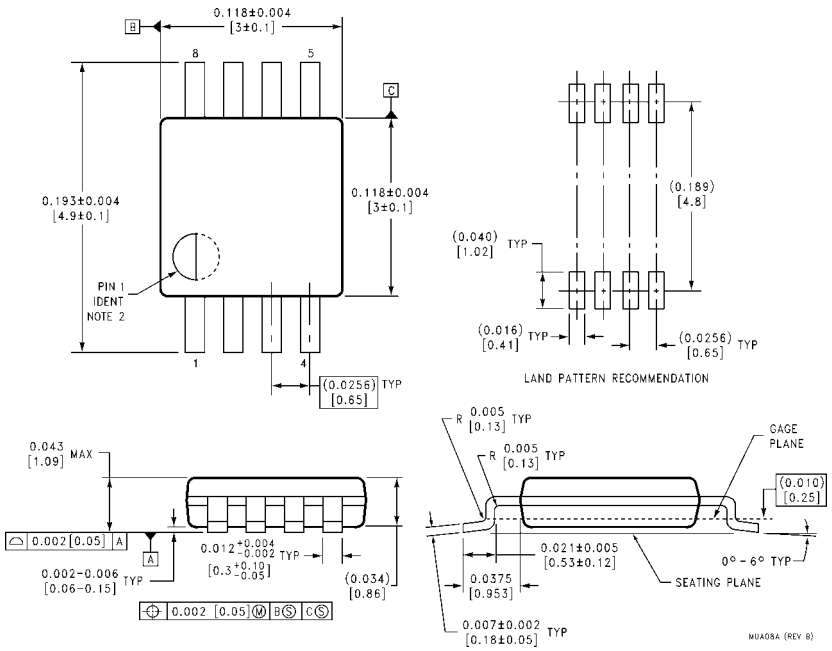
Order Number ADC08831IM or ADC08832IM
NS Package Number M08A

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



Order Number ADC08831IN, ADC08832IN
NS Package Number N08E

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



Order Number ADC08831IMM or ADC08832IMM
NS Package Number MUA08A

LIFE SUPPORT POLICY

NATIONAL'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF THE PRESIDENT OF NATIONAL SEMICONDUCTOR CORPORATION. As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury to the user.
2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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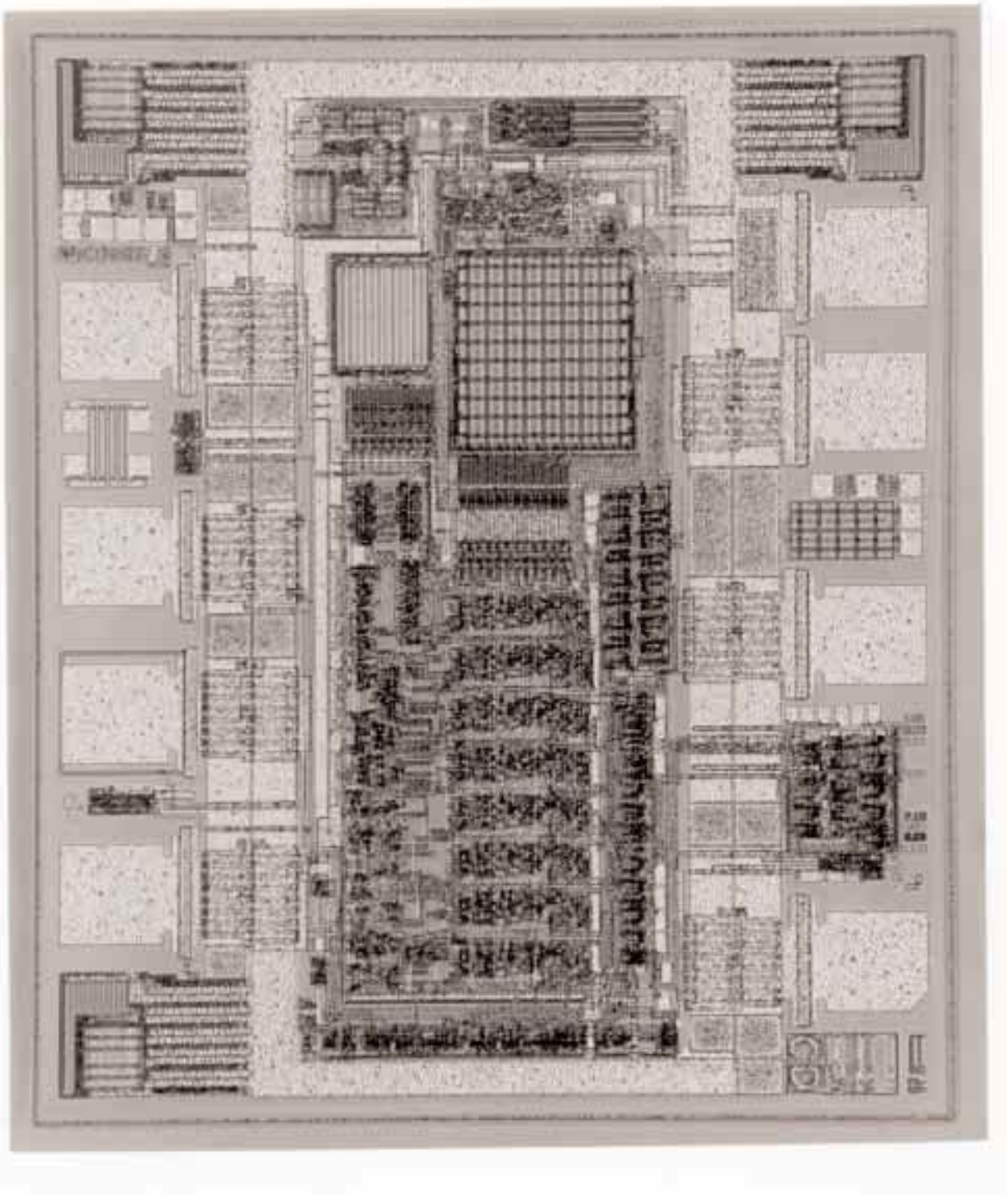
Fax: 81-3-5639-7507

National does not assume any responsibility for use of any circuitry described, no circuit patent licenses are implied and National reserves the right at any time without notice to change said circuitry and specifications.

2.2 Die Photo



3.0 PROCESS INFORMATION

3.1 Process Details

Fabrication Site: Arlington, Texas
Process Technology: 0.72 micron CMOS, Double Metal, Double Poly CS65/SP (internal name)
Wafer Diameter: 6 inches
Number of Masks: 14
Metallization: Ti/TiN/Al-Cu/TiN
Passivation: TEOS / Nitride

3.2 Process Mask Steps

Number:	Name:	Mask #
1	Twin Well	1.0
2	Composite	2.0
3	P-Field	3.0
4	Poly 1	2.8
5	ONO Protect	3.3
6	Poly 2	4.0
7	NLDD	4.5
8	N-Plus	5.0
9	P-Plus	6.0
10	Contact	7.1
11	Metal 1	8.0
12	Via 1	9.0
13	Metal 2	10.0
14	Passivation	13.0

3.3 Process Flow

1	Initial Ox
2	Twin well Pad Ox.
3	Twin Well Mask (1.0), Etch, and Implant.
4	Selective Ox.
5	Twin well Nit. Strip
6	P-well Implant
7	Selective Ox. Etch
8	N/P well Drive
9	Well Ox. Strip
10	Comp. Pad Ox.
11	Comp. Nit. Dep.
12	Comp. Mask (2.0)
13	Comp. Nit. Etch
14	P-Field Mask (3.0)
15	P-Field Implant
16	Comp. Nit. Strip

17	Comp. Pad Ox. Strip
18	Sac. Ox.
19	Poly1 Dep
20	Backside Film Removal
21	Poly1 Dope
22	Interpoly Oxide
23	Nitride Dep
24	Poly1 Mask (2.8)
25	Poly1 Etch
26	ONO Protect Mask (3.3)
27	Vt Implant
28	Oxide Etchback
29	Resist Strip
30	Gate Oxide
31	Poly Dep and Dope
32	Poly Mask (4.0)
33	Poly Etch
34	PLDD Block Mask
35	PLDD Implant
36	NLDD Block Mask (4.5)
37	NLDD Implant
38	Spacer Dep. and Etch
39	N+ Block. Mask (5.0)
40	N+ Implant
41	Poly Re-Ox.
42	P+ Block. Mask (6.0)
43	P+ Implant
44	D1 BPTEOS Dep., Reflow and Bake
45	Contact Mask (7.1) and Etch
46	Metal 1 Dep and Etch
47	Dielectric 2 Dep, Etch, and Cure.
48	Via 1 Mask (9.0) and Etch
49	Metal 2 Dep, Mask 10.0, and Etch
50	Passivation Deposit
51	Pad Mask (13.0) and Etch
52	Anneal

4.0 PACKAGING INFORMATION

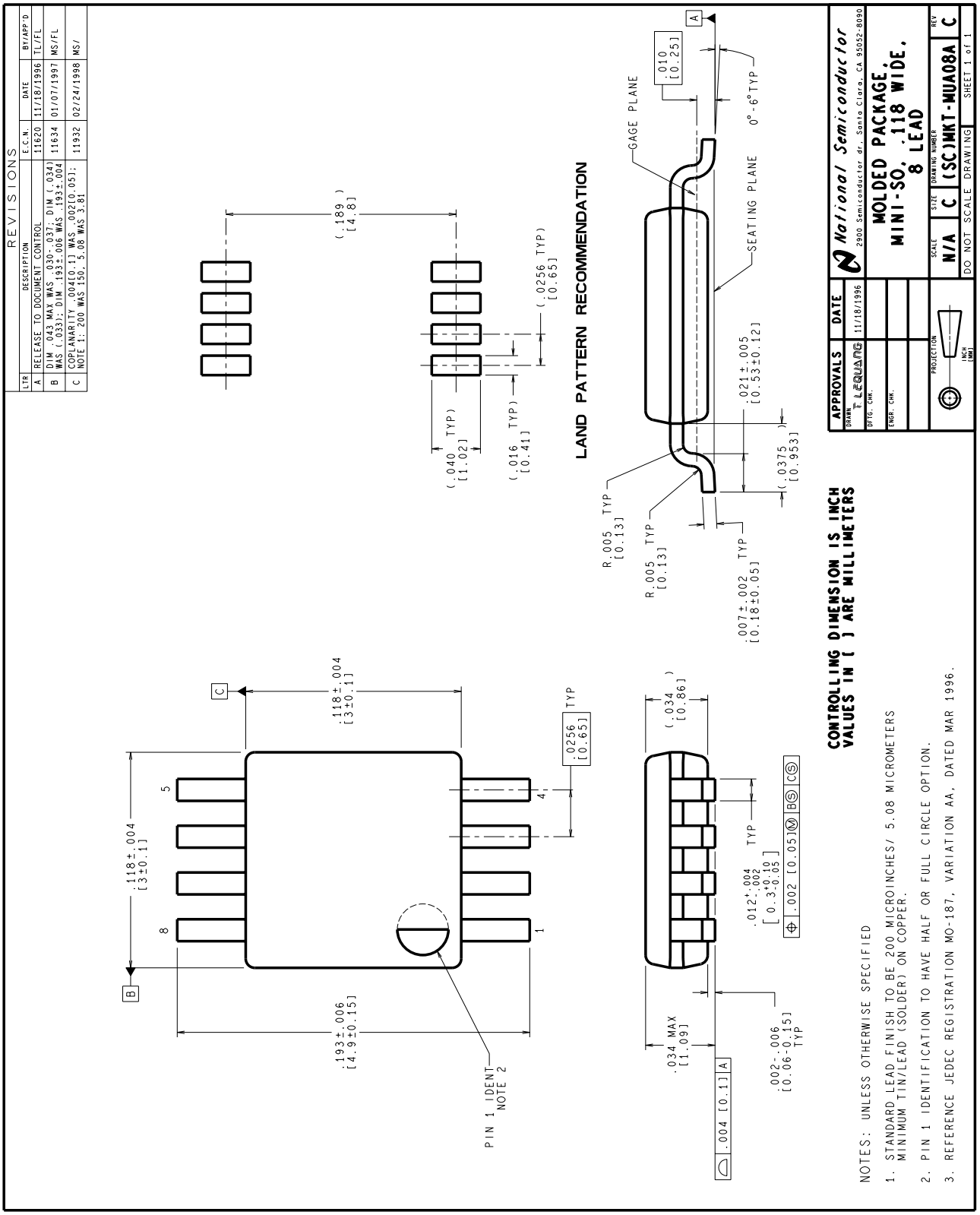
4.1 Package Material

Generic Package Type	8 Lead MSOP	8 Lead Narrow SOIC
NS Package Number	MUA08A	MO8A
Mold Compound Type	Epoxy Cresol Novolac	Epoxy Cresol Novolac
Manufacturer/Designation	Nitto MP-7400	Sumitomo EME-1100R
Lead Frame Material Manufacturer	Copper	Copper Dynacraft Inc
External Lead Frame Coating	Solder Plate Sn/Pb	Solder Plate Sn/Pb
Pins	Gull Wing	Gull Wing
Die Attached Material	Epoxy	Poly 6
Bond Wire	Gold, 1.0 mil	Gold, 1.0 mil
Bond Type	Thermosonic Ball	Thermosonic Ball
Package Thermal	235°C/W	190°C/W

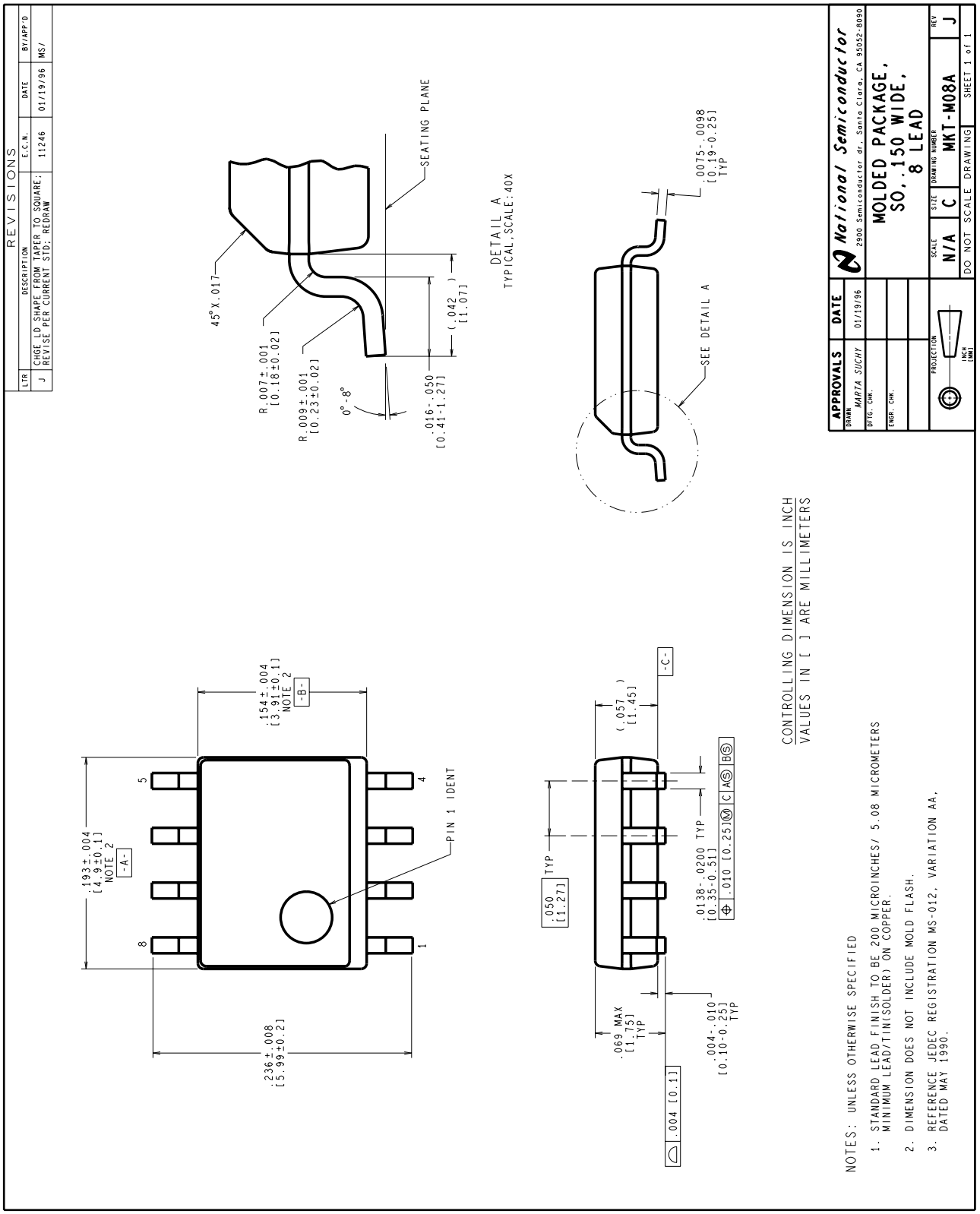
Generic Package Type	8 Lead Molded DIP	14 Lead Wide SOIC
NS Package Number	N08E	M14B
Mold Compound Type	Epoxy Cresol Novolac	Epoxy Cresol Novolac
Manufacturer/Designation	Plaskon 7115	Sumitomo EME-1100R
Lead Frame Material Manufacturer	Copper Dynacraft Inc.	Copper Dynacraft Inc
External Lead Frame Coating	Solder Plate Sn/Pb	Solder Plate Sn/Pb
Pins	Through-hole	Gull Wing
Die Attached Material	Poly 6	Poly 6
Bond Wire	Gold, 1.0 mil	Gold, 1.0 mil
Bond Type	Thermosonic Ball	Thermosonic Ball
Package Thermal	122°C/W	145°C/W

4.2 Package Dimensions

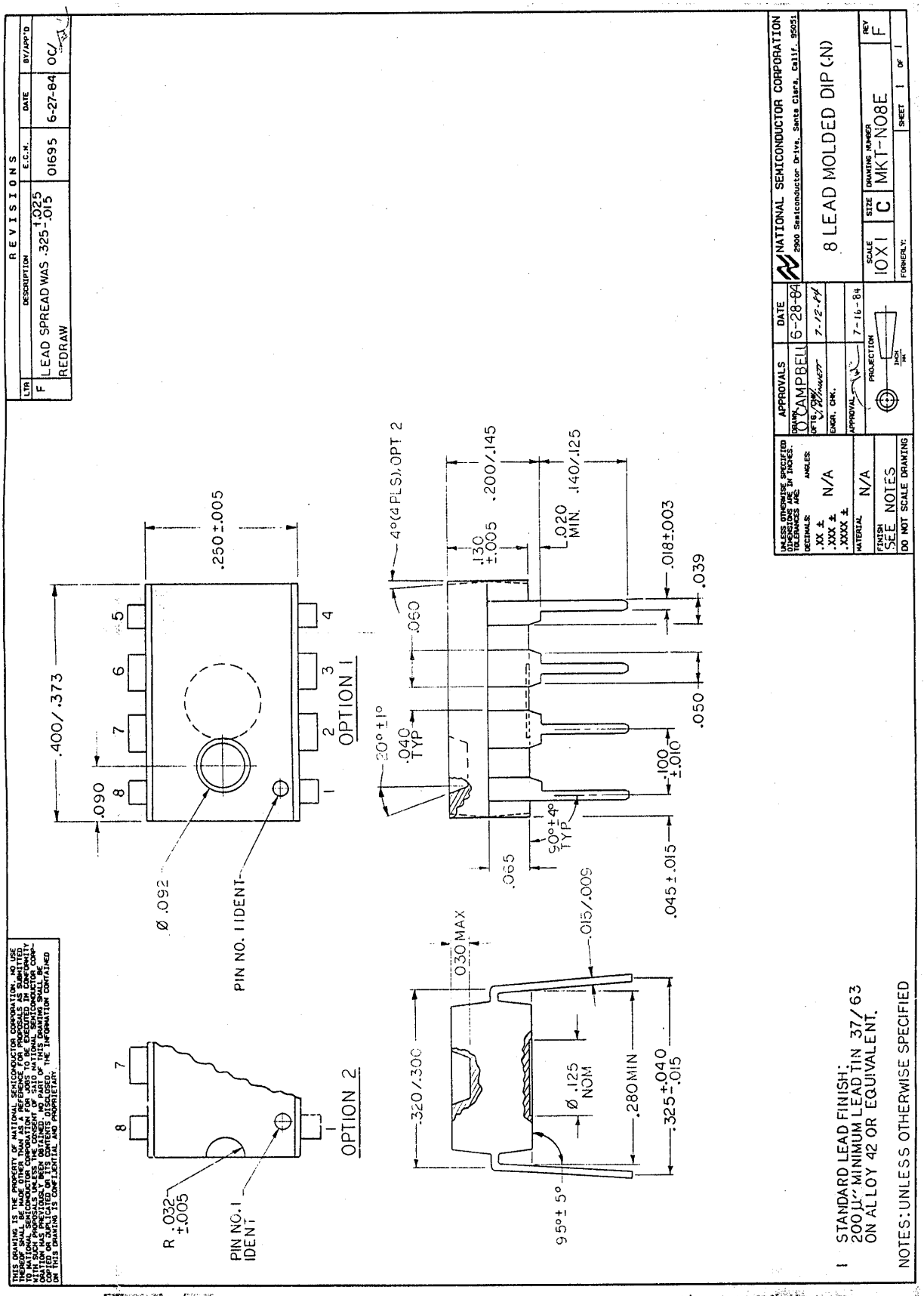
4.2.1 MSOP-8



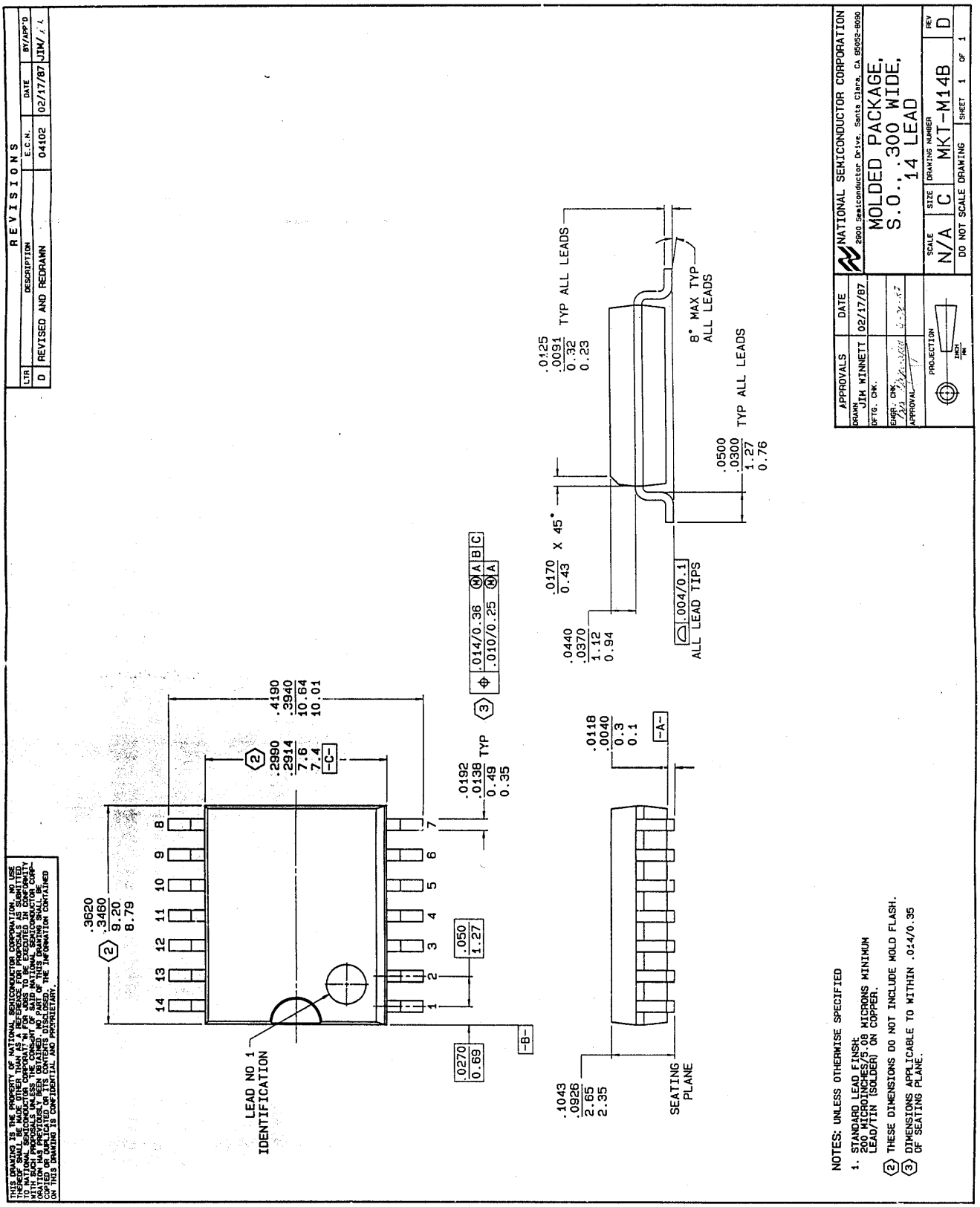
4.2.2 SOIC-8


REVISIONS
LTR
DESCRIPTION
E.C.N.
DATE
BY/APP'D
J
CHGE LD SHAPE FROM TAPER TO SQUARE; REVISE PER CURRENT STD: REDRAW
11246
01/19/96
MS/
45°X.017
R.007±.001 [0.18±0.02]
R.009±.001 [0.23±0.02]
0°-8°
.016-.050 [0.41-1.27]
SEATING PLANE
(.042) [1.07]
DETAIL A
TYPICAL, SCALE:40X
.0075-.0098 [0.19-0.25] TYP
SEE DETAIL A
.193±.004 [4.9±0.1] NOTE 2
-A-
.154±.004 [3.91±0.11] NOTE 2
-B-
PIN 1 IDENT
.236±.008 [5.99±0.2]
.050 [1.27] TYP
.069 MAX [1.75] TYP
.004-.010 [0.10-0.25] TYP
.004 [0.11]
.0138-.0200 TYP [0.35-0.51]
.010 [0.25] M C A S B S
(.057) [1.45]
-C-
CONTROLLING DIMENSION IS INCH
VALUES IN [ ] ARE MILLIMETERS
NOTES: UNLESS OTHERWISE SPECIFIED
1. STANDARD LEAD FINISH TO BE 200 MICROINCHES/ 5.08 MICROMETERS MINIMUM LEAD/TIN(SOLDER) ON COPPER.
2. DIMENSION DOES NOT INCLUDE MOLD FLASH.
3. REFERENCE JEDEC REGISTRATION MS-012, VARIATION AA, DATED MAY 1990.
APPROVALS
DRAWN MARTA SUCHY
DATE 01/19/96
DFTG. CHK.
ENGR. CHK.
PROJECTION
INCH (MM)
National Semiconductor
2900 Semiconductor dr. Santa Clara, CA 95052-8090
MOLDED PACKAGE, SO, .150 WIDE, 8 LEAD
SCALE N/A
SIZE C
DRAWING NUMBER MKT-M08A
REV J
DO NOT SCALE DRAWING
SHEET 1 of 1

4.2.3 DIP-8


REVISIONS
LTR
DESCRIPTION
E.C.N.
DATE
BY/APP'D
F
LEAD SPREAD WAS .325+.025 -.015
REDRAW
01695
6-27-84
NATIONAL SEMICONDUCTOR CORPORATION
2900 Semiconductor Drive, Santa Clara, Calif. 95051
8 LEAD MOLDED DIP (N)
APPROVALS
DRAWN
CAMPBELL
6-28-84
ENGR. CHK.
7-12-84
APPROVAL
7-16-84
PROJECTION
SCALE
10X1
SIZE
C
DRAWING NUMBER
MKT-N08E
REV
F
SHEET 1 OF 1
FORMERLY:
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES
TOLERANCES ARE:
DECIMALS
ANGLES
.XX ±
.XXX ±
.XXXX ±
N/A
MATERIAL
N/A
FINISH
SEE NOTES
DO NOT SCALE DRAWING
THIS DRAWING IS THE PROPERTY OF NATIONAL SEMICONDUCTOR CORPORATION, NO USE
.400/.373
.090
.250 ±.005
Ø .092
PIN NO. 1 IDENT
OPTION 1
R .032 ±.005
PIN NO.1 IDENT
OPTION 2
4°(4 PLS), OPT 2
.060
.130 ±.005
.200/.145
.020 MIN.
.140/.125
.018±.003
.039
.050
20° ±1°
.040 TYP
.100 ±.010
90°±4° TYP
.065
.045±.015
.320/.300
.030 MAX
.015/.009
Ø .125 NOM
.280 MIN
.325+.040 -.015
95° ± 5°
1 STANDARD LEAD FINISH:
200µ" MINIMUM LEAD TIN 37/63
ON ALLOY 42 OR EQUIVALENT.
NOTES: UNLESS OTHERWISE SPECIFIED

4.2.4 SOIC-14


REVISIONS
LTR DESCRIPTION E.C.N. DATE BY/APP'D
D REVISED AND REDRAWN 04102 02/17/87 JIM/
NATIONAL SEMICONDUCTOR CORPORATION
2900 Semiconductor Drive, Santa Clara, CA 95052-8090
MOLDED PACKAGE, S.O., .300 WIDE, 14 LEAD
SCALE N/A SIZE C DRAWING NUMBER MKT-M14B REV D
DO NOT SCALE DRAWING SHEET 1 OF 1
APPROVALS DATE
DRAWN JIM WINNETT 02/17/87
PROJECTION
NOTES: UNLESS OTHERWISE SPECIFIED
1. STANDARD LEAD FINISH: 200 MICROINCHES/5.08 MICRONS MINIMUM LEAD/TIN (SOLDER) ON COPPER.
(2) THESE DIMENSIONS DO NOT INCLUDE MOLD FLASH.
(3) DIMENSIONS APPLICABLE TO WITHIN .014/0.35 OF SEATING PLANE.
LEAD NO 1 IDENTIFICATION
SEATING PLANE
ALL LEAD TIPS
TYP ALL LEADS
8° MAX TYP ALL LEADS
THIS DRAWING IS THE PROPERTY OF NATIONAL SEMICONDUCTOR CORPORATION. NO USE OF THE INFORMATION ON THIS DRAWING IS PERMITTED WITHOUT THE WRITTEN CONSENT OF NATIONAL SEMICONDUCTOR CORPORATION. ANY PROPOSALS FOR JOBS TO BE EXECUTED IN CONFORMITY WITH SUCH PROPOSALS UNLESS THE CONSENT OF SAID NATIONAL SEMICONDUCTOR CORP. IS FIRST OBTAINED IN WRITING. ANY PROPOSALS SUBMITTED PURSUANT TO THIS DRAWING SHALL BE COPIED OR DUPLICATED OR ITS CONTENTS DISCLOSED. THE INFORMATION CONTAINED ON THIS DRAWING IS CONFIDENTIAL AND PROPRIETARY.

4.3 Tape & Reel Dimensions

For 8 lead SOIC look at dimensions in table for OPT01 (STOCK #025349)
For 14 lead SOIC look at dimensions in table for OPT02 (STOCK #025350)
For 8 lead MSOP look at dimensions in table for OPT17 (STOCK #060860)

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REVISIONS

LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
F	DELETE OPT'S 1 THRU 8 FOR SUMITOMO AND BRADY; REMOVE "VENDOR" COLUMN FROM OPT TBL; REVISE OPT'S 07 & 08 PER ECN; REDRAW ON PRO/E.	11527	08/13/1996	MS/OM
G	ADD OPTIONS 9 THRU 13 (SHT 3); ADD OPTIONS 14 THRU 16 (SHT 3); ADD OPTIONS 17 (SHT 3); UPDATE OPT TBL AND NOTES.	11543 11544 11545	10/17/1996	MS/AP
H	ADD DESIGN B OPTION TABLE FOR OPT'S 01, 04 THRU 08, 10 THRU 12, 14 & 15 (NEW SHT 2); ADD DESIGN A CALLOUT TO SHT 1.	11770	08/19/1997	MS/ [illegible]

OPT	STOCK #	PKG TYPE	TAPE	DIM A	DIM Ao	DIM B	DIM Bo	DIM C	DIM Co	DIM D	DIM Do	DIM L	DIM F	DIM G	DIM Go	DIM H	DIM Ho	DIM Ko	DIM K1	DIM P1	DIM W
17	060850	MSO-08	12mm	.213 [5.4]	.209 [5.3]	.138 [3.5]	.134 [3.4]	N/A	N/A	N/A	N/A	N/A	.217 [5.5]	N/A	N/A	N/A	N/A	.055 [1.4]	N/A	.315 [8]	.472 [12]
16	060859	SO-16N	16mm	.262 [6.65]	.256 [6.5]	.411 [10.45]	.406 [10.3]	.177 [4.5]	.138 [3.5]	.090 [2.3]	.051 [1.3]	.260 [6.6]	.295 [7.5]	N/A	N/A	N/A	N/A	.091 [2.3]	.071 [1.8]	.315 [8]	.630 [16]
15	060858	SO-14N	16mm	.262 [6.65]	.256 [6.5]	.380 [9.65]	.374 [9.5]	.177 [4.5]	.138 [3.5]	.090 [2.3]	.051 [1.3]	.260 [6.6]	.295 [7.5]	N/A	N/A	N/A	N/A	.091 [2.3]	.071 [1.8]	.315 [8]	.630 [16]
14	060857	SO-08N	12mm	.278 [7.05]	.272 [6.9]	.219 [5.55]	.213 [5.4]	N/A	N/A	N/A	N/A	N/A	.217 [5.5]	N/A	N/A	N/A	N/A	.079 [2]	.067 [1.7]	.315 [8]	.472 [12]
13	060855	SO-28W	24mm	.435 [11.05]	.429 [10.9]	.728 [18.49]	.720 [18.3]	.283 [7.2]	.244 [6.2]	.126 [3.2]	.087 [2.2]	.543 [13.8]	.453 [11.5]	N/A	N/A	N/A	N/A	.126 [3.2]	.106 [2.7]	.472 [12]	.945 [24]
12	060854	SO-24W	24mm	.431 [10.95]	.425 [10.8]	.632 [16.05]	.626 [15.9]	N/A	N/A	N/A	N/A	N/A	.453 [11.5]	.307 [7.8]	.276 [7]	.175 [4.45]	.159 [4.05]	.126 [3.2]	.110 [2.8]	.472 [12]	.945 [24]
11	060853	SO-20W	24mm	.441 [11.2]	.429 [10.9]	.535 [13.6]	.524 [13.3]	N/A	N/A	N/A	N/A	N/A	.453 [11.5]	.323 [8.2]	.276 [7]	.142 [3.6]	.118 [3]	.126 [3.2]	.106 [2.7]	.472 [12]	.945 [24]
10	060852	SO-16W	16mm	.435 [11.05]	.429 [10.9]	.429 [10.9]	.421 [10.7]	.283 [7.2]	.244 [6.2]	.098 [2.5]	.059 [1.5]	.354 [9]	.295 [7.5]	N/A	N/A	N/A	N/A	.126 [3.2]	.106 [2.7]	.472 [12]	.630 [16]
09	060851	SO-14W	16mm	.435 [11.05]	.429 [10.9]	.380 [9.65]	.374 [9.5]	.283 [7.2]	.244 [6.2]	.098 [2.5]	.059 [1.5]	.307 [7.8]	.295 [7.5]	N/A	N/A	N/A	N/A	.126 [3.2]	.106 [2.7]	.472 [12]	.630 [16]
08	025347	SO-28W	24mm	.431 [10.95]	.429 [10.9]	.726 [18.45]	.720 [18.3]	N/A	N/A	N/A	N/A	N/A	.453 [11.5]	N/A	N/A	N/A	N/A	.118 [3]	N/A	.472 [12]	.945 [24]
07	025346	SO-24W	24mm	.435 [11.05]	.425 [10.8]	.630 [16]	.626 [15.9]	N/A	N/A	N/A	N/A	N/A	.453 [11.5]	N/A	N/A	N/A	N/A	.126 [3.2]	N/A	.472 [12]	.945 [24]
06	025345	SO-20W	24mm	.435 [11.05]	.429 [10.9]	.530 [13.45]	.524 [13.3]	N/A	N/A	N/A	N/A	N/A	.453 [11.5]	N/A	N/A	N/A	N/A	.118 [3]	N/A	.472 [12]	.945 [24]
05	025344	SO-16W	16mm	.435 [11.05]	.429 [10.9]	.430 [10.91]	.421 [10.7]	N/A	N/A	N/A	N/A	N/A	.295 [7.5]	N/A	N/A	N/A	N/A	.118 [3]	N/A	.472 [12]	.630 [16]
04	025343	SO-14W	16mm	.435 [11.05]	.429 [10.9]	.380 [9.65]	.374 [9.5]	N/A	N/A	N/A	N/A	N/A	.295 [7.5]	N/A	N/A	N/A	N/A	.118 [3]	N/A	.472 [12]	.630 [16]
03	025351	SO-16N	16mm	.262 [6.65]	.256 [6.5]	.411 [10.45]	.406 [10.3]	N/A	N/A	N/A	N/A	N/A	.295 [7.5]	N/A	N/A	N/A	N/A	.083 [2.1]	N/A	.315 [8]	.630 [16]
02	025350	SO-14N	16mm	.262 [6.65]	.256 [6.5]	.380 [9.65]	.374 [9.5]	N/A	N/A	N/A	N/A	N/A	.295 [7.5]	N/A	N/A	N/A	N/A	.083 [2.1]	N/A	.315 [8]	.630 [16]
01	025349	SO-08N	12mm	.264 [6.7]	.256 [6.5]	.213 [5.4]	.209 [5.3]	N/A	N/A	N/A	N/A	N/A	.217 [5.5]	N/A	N/A	N/A	N/A	.083 [2.1]	N/A	.315 [8]	.472 [12]

NOTES: UNLESS OTHERWISE SPECIFIED

1. CUMMULATIVE PITCH TOLERANCE FOR FEEDING HOLES AND CAVITIES (CHIP POCKETS) NOT TO EXCEED .008[0.20] OVER 10 PITCH SPAN.
2. SMALLEST ALLOWABLE BENDING RADIUS.
3. THRU HOLE INSIDE CAVITY IS CENTERED WITHIN CAVITY.
4. TOLERANCE IS ±.002[0.05] FOR THESE DIMENSIONS ON ALL 12mm TAPES.
5. Ao AND Bo MEASURED ON A PLANE .012in/ 0.3mm ABOVE THE BOTTOM OF THE POCKET.
6. Ko MEASURED FROM A PLANE ON THE INSIDE BOTTOM OF THE POCKET TO THE TOP SURFACE OF THE CARRIER.
7. POCKET POSITION RELATIVE TO SPROCKET HOLE MEASURED AS TRUE POSITION OF POCKET, NOT POCKET HOLE.
8. CONTROLLING DIMENSION IS MILLIMETER, DIMENSIONS IN INCHES ROUNDED.

DESIGN A

QUALITY ASSURANCE PROVISIONS
Requirements shall be in accordance with NSC Mat'l Procurement Specifica-tion 98081 and as specified herein. The procuring activity reserves the right to perform inspection in accordance with this specification and to return shipments that fail.

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES. TOLERANCES ARE:
DECIMALS: ANGLES:
.XX ± N/A ± N/A
.XXX ± .004[0.10]
XXXX ± N/A
MATERIAL: BLK COND, POLYSTYRENE
FINISH: N/A
DO NOT SCALE DRAWING

APPROVALS	DATE
DRAWN: MARTA SUCHY	08/13/1996
ENG. CHG: [signature]	08/13/97
ENG. CHG: [signature]	08/28/97

PROJECTION: [illegible] INCH [mm]

National Semiconductor
2900 Semiconductor dr., Santa Clara, CA 95052-8090

TAPE, EMBOSSED, 12, 16 AND 24mm, SOIC

SCALE	SIZE	DRAWING NUMBER	REV
10X	D	(SC)39-1997	H

FORMERLY: N/A | SHEET 1 of 4

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REVISIONS				
LTR	DESCRIPTION	E.C.R.	DATE	BY/APP'D
-	SEE SHEET 1			

OPT	STOCK #	PKG TYPE	TAPE	DIM A	DIM Ao	DIM B	DIM Bo	DIM C	DIM Co	DIM D	DIM Do	DIM L	DIM F	DIM G	DIM Go	DIM H	DIM Ho	DIM Ko	DIM K1	DIM P1	DIM W
15	060858	SO-14N	16mm	.262 [6.65]	.256 [6.5]	.366 [9.3]	.362 [9.2]	N/A	N/A	N/A	N/A	N/A	.295 [7.5]	.177 [4.5]	.150 [3.8]	.102 [2.6]	.083 [2.1]	.091 [2.3]	.071 [1.8]	.315 [8]	.630 [16]
14	060857	SO-08N	12mm	.258 [6.55]	.252 [6.4]	.209 [5.3]	.205 [5.2]	N/A	N/A	N/A	N/A	N/A	.217 [5.5]	N/A	N/A	N/A	N/A	.091 [2.3]	.071 [1.8]	.315 [8]	.472 [12]
12	060854	SO-24W	24mm	.439 [11.15]	.429 [10.9]	.634 [16.1]	.626 [15.9]	N/A	N/A	N/A	N/A	N/A	.453 [11.5]	.307 [7.8]	.276 [7]	.214 [5.4]	.193 [4.9]	.126 [3.2]	.106 [2.7]	.472 [12]	.945 [24]
11	060853	SO-20W	24mm	.439 [11.15]	.429 [10.9]	.533 [13.55]	.524 [13.3]	N/A	N/A	N/A	N/A	N/A	.453 [11.5]	.323 [8.2]	.283 [7.2]	.150 [3.8]	.126 [3.2]	.126 [3.2]	.106 [2.7]	.472 [12]	.945 [24]
10	060852	SO-16W	16mm	.439 [11.15]	.429 [10.9]	.437 [11.1]	.425 [10.8]	N/A	N/A	N/A	N/A	N/A	.295 [7.5]	.307 [7.8]	.276 [7]	.114 [2.9]	.094 [2.4]	.126 [3.2]	.106 [2.7]	.472 [12]	.630 [16]
08	025347	SO-28W	24mm	.431 [10.95]	.425 [10.8]	.,.6 [18.45]	.717 [18.2]	N/A	N/A	N/A	N/A	N/A	.453 [11.5]	N/A	N/A	N/A	N/A	.110 [2.8]	N/A	.472 [12]	.945 [24]
07	025346	SO-24W	24mm	.437 [11.1]	.429 [10.9]	.630 [16]	.624 [15.85]	N/A	N/A	N/A	N/A	N/A	.453 [11.5]	N/A	N/A	N/A	N/A	.118 [3]	N/A	.472 [12]	.945 [24]
06	025345	SO-20W	24mm	.436 [11.08]	.429 [10.9]	.530 [13.45]	.524 [13.3]	N/A	N/A	N/A	N/A	N/A	.453 [11.5]	N/A	N/A	N/A	N/A	.118 [3]	N/A	.472 [12]	.945 [24]
05	025344	SO-16W	16mm	.441 [11.20]	.429 [10.9]	.431 [10.96]	.424 [10.76]	N/A	N/A	N/A	N/A	N/A	.295 [7.5]	N/A	N/A	N/A	N/A	.118 [3]	N/A	.472 [12]	.630 [16]
04	025343	SO-14W	16mm	.439 [11.15]	.429 [10.9]	.380 [9.65]	.374 [9.5]	N/A	N/A	N/A	N/A	N/A	.295 [7.5]	N/A	N/A	N/A	N/A	.118 [3]	N/A	.472 [12]	.630 [16]
01	025349	SO-08N	12mm	.262 [6.65]	.252 [6.4]	.213 [5.4]	.205 [5.2]	N/A	N/A	N/A	N/A	N/A	.217 [5.5]	N/A	N/A	N/A	N/A	.083 [2.1]	N/A	.315 [8]	.472 [12]

DESIGN B

QUALITY ASSURANCE PROVISIONS
Requirements shall be in accordance with NSC Mil-I Procurement Specification #8081 and as specified herein. The procuring activity reserves the right to perform inspection in accordance with this specification and to return shipments that fail.

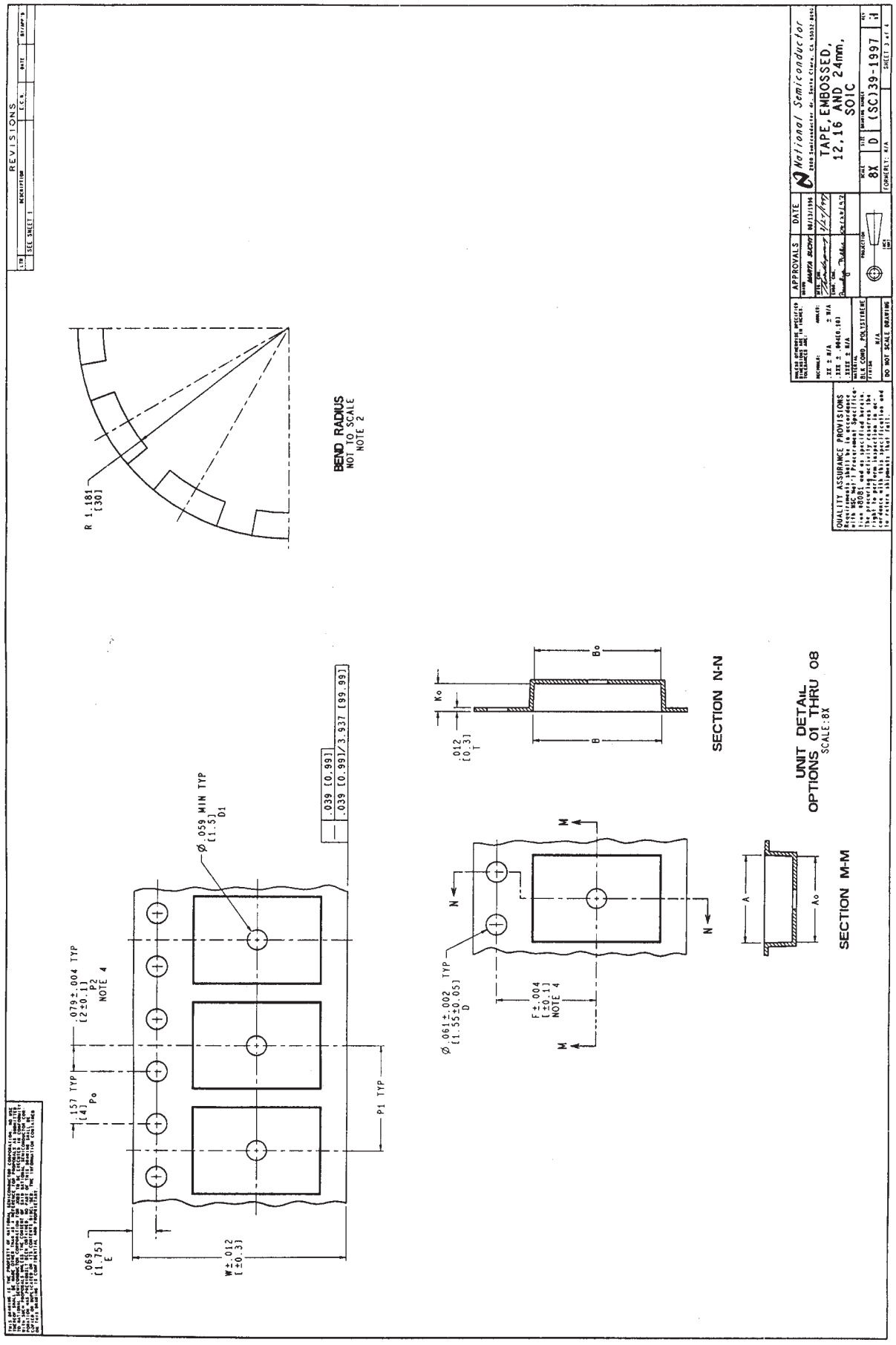
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES. TOLERANCES ARE:
DECIMALS: ANGLES:
.XX ± N/A ± N/A
.XXX ± .004[0.10]
.XXXX ± N/A
MATERIAL: BLK COND, POLYSTYRENE
FINISH: N/A
DO NOT SCALE DRAWING

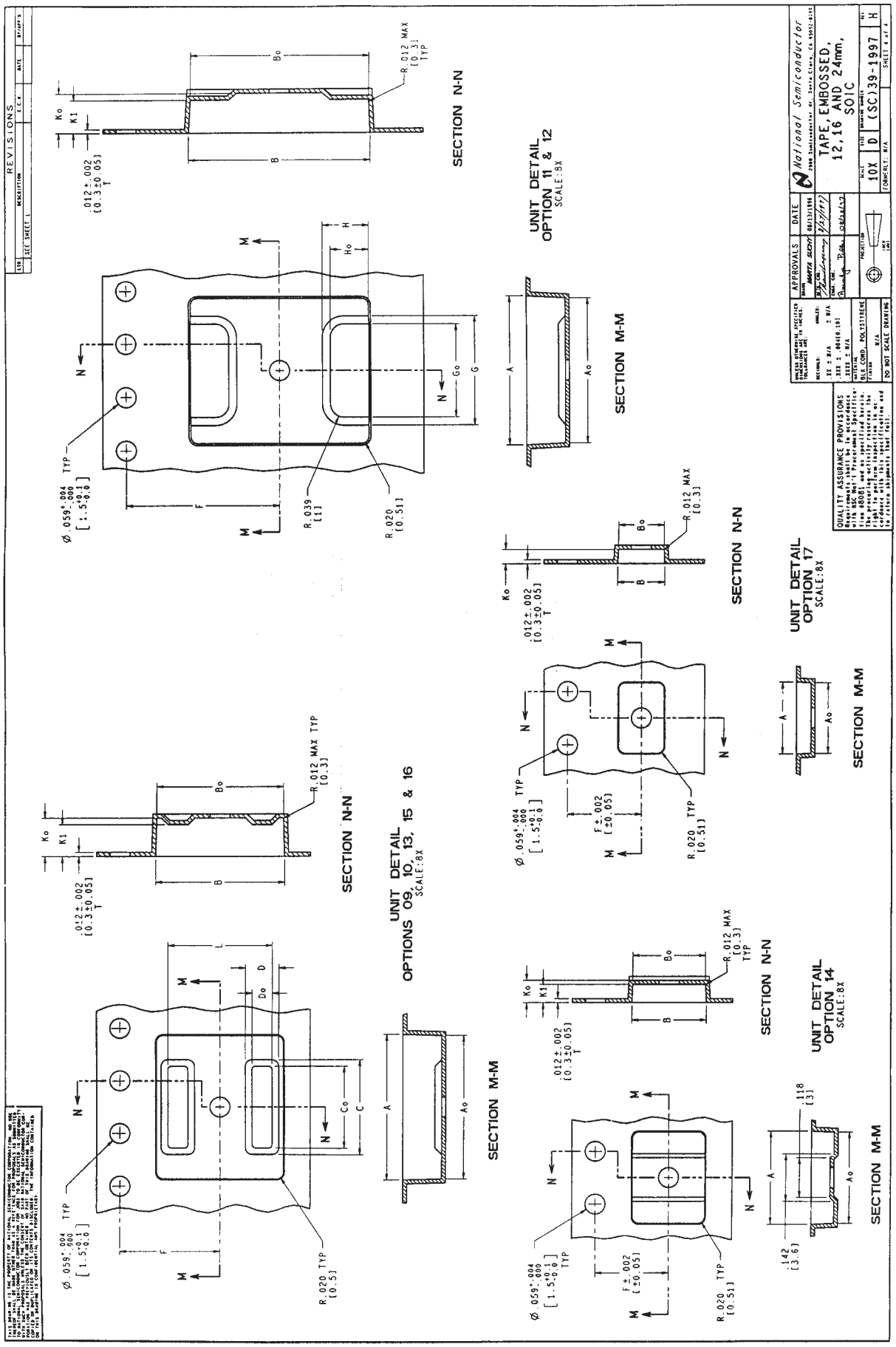
APPROVALS	DATE
DRAWN: MARTA SUCHY	08/13/1996
ENGR:	8/21/1997
PROJECT ENGR:	08/13/97

National Semiconductor
2900 Semiconductor dr, Santa Clara, CA 95052-8090

TAPE, EMBOSSED, 12,16 AND 24mm, SOIC

PROJECTION | SCALE: 10X | SIZE: D | DRAWING NUMBER: (SC)39-1997 | REV: H
FORMERLY: N/A | SHEET 2 of 4


REVISIONS
SEE SHEET 1
R 1.181 [30]
BEND RADIUS
NOT TO SCALE
NOTE 2
.039 [0.99]
.039 [0.991/3.937 [99.99]
Ø .059 MIN TYP [1.5] D1
.157 TYP [4] Po
.079±.004 [2±0.1] P2 NOTE 4
P1 TYP
.069 [1.75] E
W±.012 [±0.3]
Ø .061±.002 TYP [1.55±0.05] D
F±.004 [±0.1] NOTE 4
.012 [0.3]
Ko
Bo
B
SECTION N-N
SECTION M-M
UNIT DETAIL
OPTIONS 01 THRU 08
SCALE: 8X
QUALITY ASSURANCE PROVISIONS
APPROVALS
DATE
National Semiconductor
TAPE, EMBOSSED, 12, 16 AND 24mm, SOIC
8X
D
(SC)39-1997
DO NOT SCALE DRAWING


REVISIONS
SEE SHEET 1
APPROVALS
DATE
National Semiconductor
TAPE, EMBOSSED, 12, 16 AND 24mm, SOIC
10X
D
(SC)39-1997
H
SHEET 4 of 4
DO NOT SCALE DRAWING
QUALITY ASSURANCE PROVISIONS
SECTION N-N
SECTION M-M
UNIT DETAIL OPTION 11 & 12
SCALE:8X
UNIT DETAIL OPTIONS 09, 10, 13, 15 & 16
SCALE:8X
UNIT DETAIL OPTION 17
SCALE:8X
UNIT DETAIL OPTION 14
SCALE:8X
R.012 MAX [0.3] TYP
R.020 TYP [0.51]
R.039 [1]
.012±.002 [0.3±0.05] T
Ø.059+.004 -.000 [1.5+0.1 -0.0] TYP
F±.002 [±0.05]
.118 [3]
.142 [3.6]

5.0 RELIABILITY DATA

5.1 ADC08831 Reliability Report

National Semiconductor

Reliability Test Report

Purpose

ADC08831 NEW DEVICE QUALIFICATION

Approvals

Reliability Engineer

Mgr Ref Engineering

Reference File Numbers

RSC199802600	RSC199802243
RSC199802556	RSC199802512
RSC199801615	RSC1998023472
RSC199801672	Q19970301
RSC199801734	

Distribution List

Nick Stanco
Jim Dreyfus

Abstract

The ADC08831 8-Bit Serial I/O A/D Converter with Multiplexer Options was subjected to reliability testing per qual plan Q19970301 for qualification as a new device for the Amplifiers product line. All testing other than ESD and Latch-up was performed on the ADC08832 (2-channel version nearly identical to the ADC08831) with all required testing completed without failure. The ADC08831 has passed all required ESD and Latch-up tests. The ADC08831 in the 8L MDIP, 8L SOIC, 14L WIDE SOIC and the 8L MSOP packages is now released to production.

Description

Test Request	Device Name	Sbgp	Wafer Die Run	Fab Loc	Fab Line	Pkg Code	# Leads	Assy Loc	Mold Cmpd
RSC199801615	ADC08832CIN	A	TE	FAB II	N\MDIP	8	EM	9818	B8
RSC199801672	ADC08832CIMM	A	TE	FAB II	N\MMSO	8	EM		B14
RSC199802556	ADC08832IN	D	TE	FAB II	N\MDIP	8	EM		B8
RSC199801734	ADC08832CIWM	A	TE	FAB II	N\MSOW	14	EM	9818	B14
RSC199802243	ADC08832CIN	B	TE	FAB II	N\MDIP	8	EM	9824	B8
RSC199802512	ADC08832CIN	D	TE	FAB II	N\MDIP	8	EM		B8
RSC199802600	ADC08832IN	D	TE	FAB II	N\MDIP	8	EM		B8
RSC199803472	ADC08831N	D	TE	FAB II	N\MDIP	8	EM		B8

Tests Performed

Test: Autoclave Test (ACLV)

Test Request	Device	Sbgrp	Rel Humidity	Pressure	High Temp	LowTemp
RSC199801615	ADC08832CIN	A	100	15	121	
RSC199801672	ADC08832CIMM	A	100	15	121	
RSC199801734	ADC08832CIWM	A	100	15	121	

5.0 RELIABILITY DATA

Tests Performed

Test: High Temperature Storage test (BAKE)

Test Request	Device	Sbgrp	Rel Humidity	Pressure	High Temp	LowTemp
RSC199801615	ADC08832CIN	A			150	
RSC199801672	ADC08832CIMM	A			150	
RSC199801734	ADC08832CIWM	A			150	

Test: Operating Life Test (Dynamic) (DOPL)

Test Request	Device	Sbgrp	Rel Humidity	Pressure	High Temp	LowTemp
RSC199801615	ADC08832CIN	A			150	
RSC199802243	ADC08832CIN	B			150	
RSC199802512	ADC08832CIN	D			150	

Test: Temperature Cycle (TMCL)

Test Request	Device	Sbgrp	Rel Humidity	Pressure	High Temp	LowTemp
RSC199801615	ADC08832CIN	A			150	-65
RSC199801672	ADC08832CIMM	A			150	-65
RSC199801734	ADC08832CIWM	A			150	-65

Test: Temperature Humidity Bias Test (THBT)

Test Request	Device	Sbgrp	Rel Humidity	Pressure	High Temp	LowTemp
RSC199801615	ADC08832CIN	A	85		85	
RSC199801672	ADC08832CIMM	A	85		85	
RSC199801734	ADC08832CIWM	A	85		85	

Test: Electrostatic Discharge - Human Body Model (ESDH)

Test Request	Device	Method
RSC199803472	ADC08831IN	ATE
(Tst# 1)	Sublot	Voltage
	1	500
	2	1000
	3	1500
	4	2000
	5	2500

Test: Electrostatic Discharge - Machine Model (ESDM)

Test Request	Device	Method
RSC199803472	ADC08831IN	ATE
(Tst# 2)	Sublot	Voltage
	1	50
	2	100
	3	150
	4	200
	5	250

Test: Latch Up -Static (LUPS)

Test Request	Device	Fail Criteria		Method
RSC199802600	ADC08831IN	0002	ATE	
(Tst# 1)	Sublot	Temp		
	1	25		
	2	85		

Results and Discussion for Environmental Tests

Tests	Timepoints	8L MDIP	14L WIDE SOIC	8L MSOP
DOPL – LOT 1 (REV A)	1000 hours	0/77		
DOPL – LOT 2 (REV A)	1000 hours	0/77		
DOPL – LOT 3 (REV A)	500	0/77		
Autoclave	Post Precondition	0/77	0/75	0/77
	168 hours	0/77	0/75	0/77
Temperature Humidity Bias	Post Precondition	0/77	0/77	0/77
	168 hours	0/77	0/77	0/77
	500 hours	0/77	0/77	0/77
	1000 hours	0/77	0/77	0/77
BAKE	168 hours	0/77	0/77	0/77
	500 hours	0/77	0/77	0/77
	1000 hours	0/77	0/77	0/77
Temperature Cycle	Post Precondition	0/77	0/77	0/77
	500 cycles	0/77	0/77	0/77
	1000	0/77	0/77	0/77

ESD and Latch-up results

Tests	Voltage Level/Temperature	Number of Failures
ESD Human Body Model	500 volts	0/4
	1000	0/4
	1500	0/4
	2000	0/4
	2500	0/4
ESD Machine Model	50 volts	0/4
	100	0/4
	150	0/4
	200	0/4
	250	0/4
Latch-up	25°C @ 200mA	0/4
	85°C @ 200mA	0/4

Conclusion

The ADC08831 is in the 8L MDIP, 8L SOIC, 14L WIDE SOIC and the 8L MSOP package is now fully qualified and released to production.

5.2 ADC08832 Reliability Report

National Semiconductor

Reliability Test Report

File Number: FSC19980431
Originator: Nick Stanco
Date: September 25, 1998

Purpose

ADC08832 NEW DEVICE QUALIFICATION

Approvals

Reliability Engineer

Mgr Ref Engineering

Reference File Numbers

RSC199800644
RSC199702347
RSC199702260
RSC199700160
Q19960526

Distribution List

Nick Stanco
Jim Dreyfus
David Vieira

Abstract

The ADC08832 8-Bit Serial I/O A/D Converter with Multiplexer Options was subjected to reliability testing per qual plan Q19970301 for qualification as a new device for the Amplifiers product line. The qual plan was written to cover the release of both the ADC08832 and the ADC08831, but this report and product release applies only to the ADC08832 at this time. The ADC08832 has successfully completed all required environmental and electrical reliability tests without the occurrence of a valid failure. The ADC08832 in the 8L MDIP, 8L SOIC, 14L WIDE SOIC and the 8L MSOP packages is now fully qualified and released to production.

Description

Test Request	Device Name	Sbgp	Wafer Die Run	Fab Loc	Fab Line	Pkg Code	# Leads	Assy Loc	Mold Cmpd
RSC199801615	ADC08832CIN	A	TE	FAB II	N\MDIP	8	EM	9818	B8
RSC199801672	ADC08832CIMM	A	TE	FAB II	N\MMSO	8	EM		B14
RSC199802556	ADC08832IN	D	TE	FAB II	N\MDIP	8	EM		B8
RSC199801734	ADC08832CIWM	A	TE	FAB II	N\MSOW	14	EM	9818	B14
RSC199802243	ADC08832CIN	B	TE	FAB II	N\MDIP	8	EM	9824	B8
RSC199802512	ADC08832CIN	D	TE	FAB II	N\MDIP	8	EM		B8
RSC199802600	ADC08832IN	D	TE	FAB II	N\MDIP	8	EM		B8

Tests Performed

Test: Autoclave Test (ACLV)

Test Request	Device	Sbgrp	Rel Humidity	Pressure	High Temp	LowTemp
RSC199801615	ADC08832CIN	A	100	15	121	
RSC199801672	ADC08832CIMM	A	100	15	121	
RSC199801734	ADC08832CIWM	A	100	15	121	

Tests Performed (cont)

Test: High Temperature Storage test (BAKE)

Test Request	Device	Sbgrp	Rel Humidity	Pressure	High Temp	LowTemp
RSC199801615	ADC08832CIN	A			150	
RSC199801672	ADC08832CIMM	A			150	
RSC199801734	ADC08832CIWM	A			150	

Test: Operating Life Test (Dynamic) (DOPL)

Test Request	Device	Sbgrp	Rel Humidity	Pressure	High Temp	LowTemp
RSC199801615	ADC08832CIN	A			150	
RSC199802243	ADC08832CIN	B			150	
RSC199802512	ADC08832CIN	D			150	

Test: Temperature Cycle (TMCL)

Test Request	Device	Sbgrp	Rel Humidity	Pressure	High Temp	LowTemp
RSC199801615	ADC08832CIN	A			150	-65
RSC199801672	ADC08832CIMM	A			150	-65
RSC199801734	ADC08832CIWM	A			150	-65

Test: Temperature Humidity Bias Test (THBT)

Test Request	Device	Sbgrp	Rel Humidity	Pressure	High Temp	LowTemp
RSC199801615	ADC08832CIN	A	85		85	
RSC199801672	ADC08832CIMM	A	85		85	
RSC199801734	ADC08832CIWM	A	85		85	

Test: Electrostatic Discharge - Human Body Model (ESDH)

Test Request	Device	Method
RSC199802556	ADC08832IN	ATE
(Tst# 1)	Sublot	Voltage
	1	500
	2	600
	3	700
	4	800
	5	900
	6	1000
	7	1500
	8	2000

Test: Electrostatic Discharge - Machine Model (ESDM)

Test Request	Device	Method
RSC199802556	ADC08832IN	ATE
(Tst# 2)	Sublot	Voltage
	1	50
	2	100
	3	150
	4	200

Test: Latch Up -Static (LUPS)

Test Request	Device	Fail Criteria		Method
RSC199802600	ADC08832IN	0002	ATE	
(Tst# 1)	Sublot	Temp		
	1	25		
	2	85		
	3			

Results/Discussion

Test: Autoclave Test (ACLV)

Test Request	Device	Sbgrp	TP	Duration	Sample Size	Rejects
RSC199801615	ADC08832CIN	A	1	168	77	0
RSC199801672	ADC08832CIMM	A	1	168	77	0
RSC199801734	ADC08832CIWM	A	1	168	75	0

Test: High Temperature Storage test (BAKE)

Test Request	Device	Sbgrp	TP	Duration	Sample Size	Rejects
RSC199801615	ADC08832CIN	A	1	168	77	0
RSC199801615	ADC08832CIN	A	2	500	77	0
RSC199801615	ADC08832CIN	A	3	1000	77	0
RSC199801672	ADC08832CIMM	A	1	168	76	0
RSC199801672	ADC08832CIMM	A	2	500	76	0
RSC199801672	ADC08832CIMM	A	3	1000	76	0
RSC199801734	ADC08832CIWM	A	1	168	77	1
RSC199801734	ADC08832CIWM	A	2	500	76	0
RSC199801734	ADC08832CIWM	A	3	1000	76	0

Test: Operating Life Test (Dynamic) (DOPL)

Test Request	Device	Sbgrp	TP	Duration	Sample Size	Rejects
RSC199801615	ADC08832CIN	A	1	168	77	0
RSC199801615	ADC08832CIN	A	2	500	77	0
RSC199801615	ADC08832CIN	A	3	1000	77	0
RSC199802243	ADC08832CIN	B	1	168	77	0
RSC199802243	ADC08832CIN	B	2	500	77	0
RSC199802243	ADC08832CIN	B	3	1000	77	0
RSC199802512	ADC08832CIN	D	1	168	77	0
RSC199802512	ADC08832CIN	D	2	500	77	0

Test: Temperature Humidity Bias Test (THBT)

Test Request	Device	Sbgrp	TP	Duration	Sample Size	Rejects
RSC199801615	ADC08832CIN	A	1	168	77	0
RSC199801615	ADC08832CIN	A	2	500	77	0
RSC199801615	ADC08832CIN	A	3	1000	77	0
RSC199801672	ADC08832CIMM	A	1	168	77	0
RSC199801672	ADC08832CIMM	A	2	500	77	0
RSC199801672	ADC08832CIMM	A	4	1024	77	0
RSC199801734	ADC08832CIWM	A	1	168	76	0
RSC199801734	ADC08832CIWM	A	2	500	76	0

Test: Temperature Cycle (TMCL)

Test Request	Device	Sbgrp	TP	Duration	Sample Size	Rejects
RSC199801615	ADC08832CIN	A	1	500	77	0
RSC199801615	ADC08832CIN	A	2	1000	77	0
RSC199801672	ADC08832CIMM	A	1	500	77	0
RSC199801672	ADC08832CIMM	A	2	1000	77	0
RSC199801734	ADC08832CIWM	A	1	500	77	0
RSC199801734	ADC08832CIWM	A	2	1000	77	0

Results/Discussion (cont)

Test: Electrostatic Discharge - Human Body Model (ESDH)

Test Request	Device	Sbgrp	Sublot	Voltage	SS	#Failures	#ETRejects
RSC199802556	ADC08832IN	D	1	500	5	0	0
RSC199802556	ADC08832IN	D	2	600	5	0	0
RSC199802556	ADC08832IN	D	3	700	5	0	0
RSC199802556	ADC08832IN	D	4	800	5	0	0
RSC199802556	ADC08832IN	D	5	900	5	0	0
RSC199802556	ADC08832IN	D	6	1000	5	0	0
RSC199802556	ADC08832IN	D	7	1500	5	0	0
RSC199802556	ADC08832IN	D	8	2000	5	0	0

Test: Electrostatic Discharge - Machine Model (ESDM)

Test Request	Device	Sbgrp	Sublot	Voltage	SS	#Failures	#ETRejects
RSC199802556	ADC08832IN	D	2	100	5	0	0
RSC199802556	ADC08832IN	D	3	150	5	0	0
RSC199802556	ADC08832IN	D	4	200	5	0	0

Test: Latch Up -Static (LUPS)

Test Request	Device	Sbgrp	Sublot	Temp	SS	#Failures	#ETRejects
RSC199802600	ADC08832IN	D	1	500	5	0	0
RSC199802600	ADC08832IN	D	2	600	5	0	0

Conclusion

National Semiconductor supplies a comprehensive set of service and support capabilities. Complete product information and design support is available from National's customer support centers.

To receive sales literature and technical assistance, contact the National support center in your area.

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